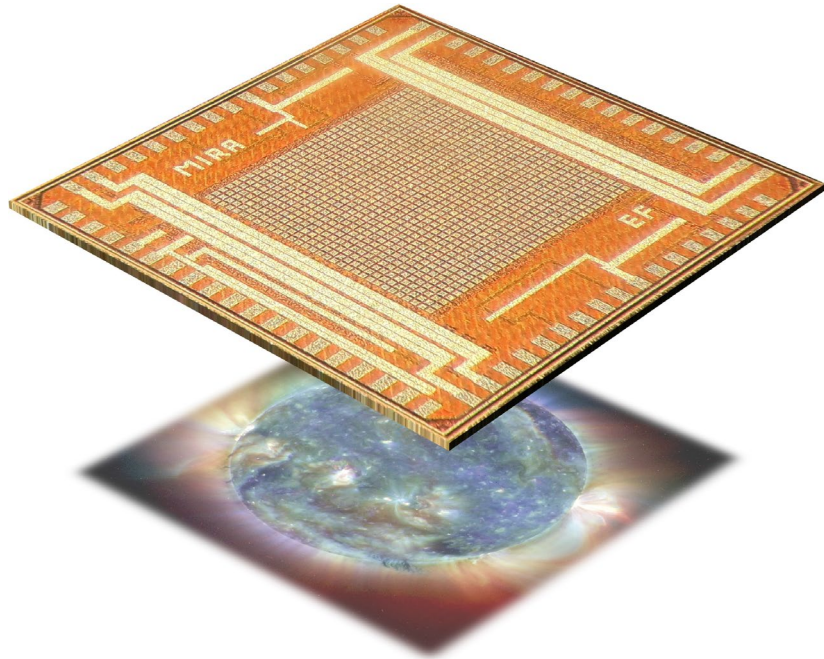




RadLab  
POLITECNICO  
MILANO 1863



# MIRA: a Low-Noise ASIC with 35 $\mu\text{m}$ Pixel Pitch for the Readout of Microchannel Plates

E. Fabbrica, D. Butta, L. Nassi, J. E. Nino, L. Zorzato, M. Carminati, C. Fiorini

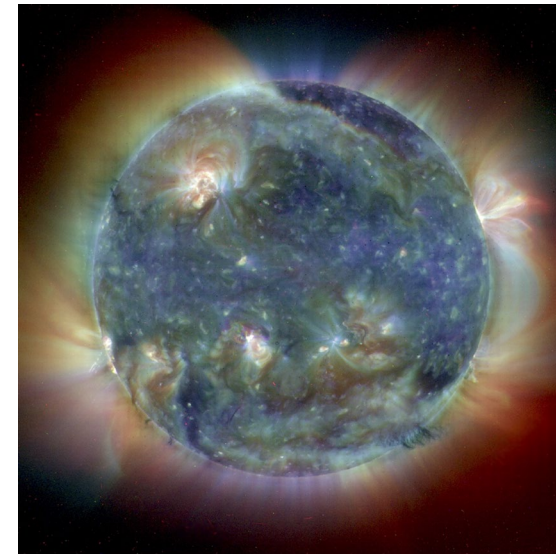
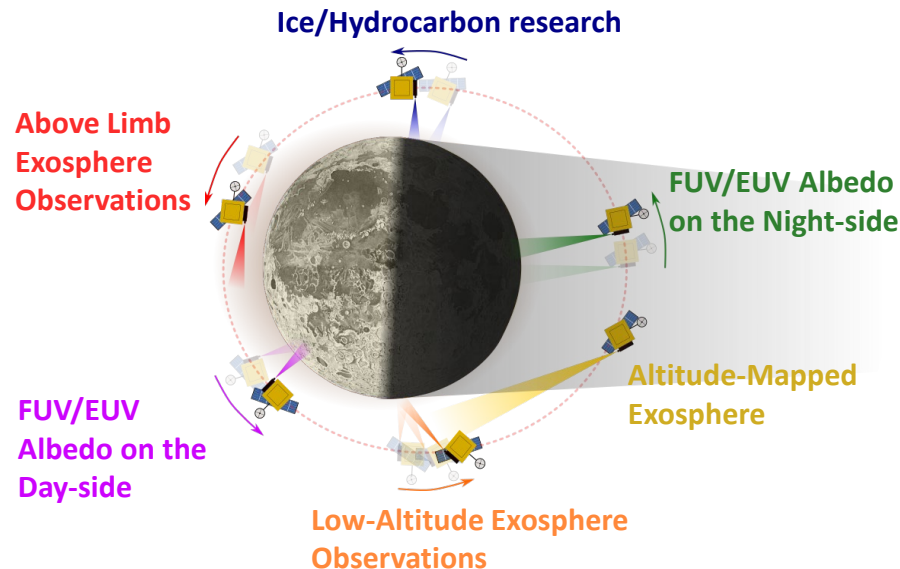
*Politecnico di Milano, Dipartimento di Elettronica, Informazione e Bioingegneria, Milano, Italy*

*Work supported by ASI (Italian Space Agency) within the PLUS project*

- Ultraviolet Astronomy and Microchannel Plates (MCP) Detectors
- The MIRA readout ASIC for MCPs
- Charge Sensitive Preamplifier
- Pixels summing stage and discriminator
- Charge sharing arbitration
- Experimental results (MIRA I and MIRA II)
- First operation with MCP
- Conclusions and future work

## FUV/EUV Imaging Spectrometry:

- To probe the **exospheres** (direct detection) and the **highest-altitude atmospheres** (through stellar occultation) of planets and satellites, including the **Moon**
- To determine **constituents**, study the atmosphere dynamics, and understand the **formation mechanisms** and the **surface release** processes
- To investigate auroras occurring on **giant planets**

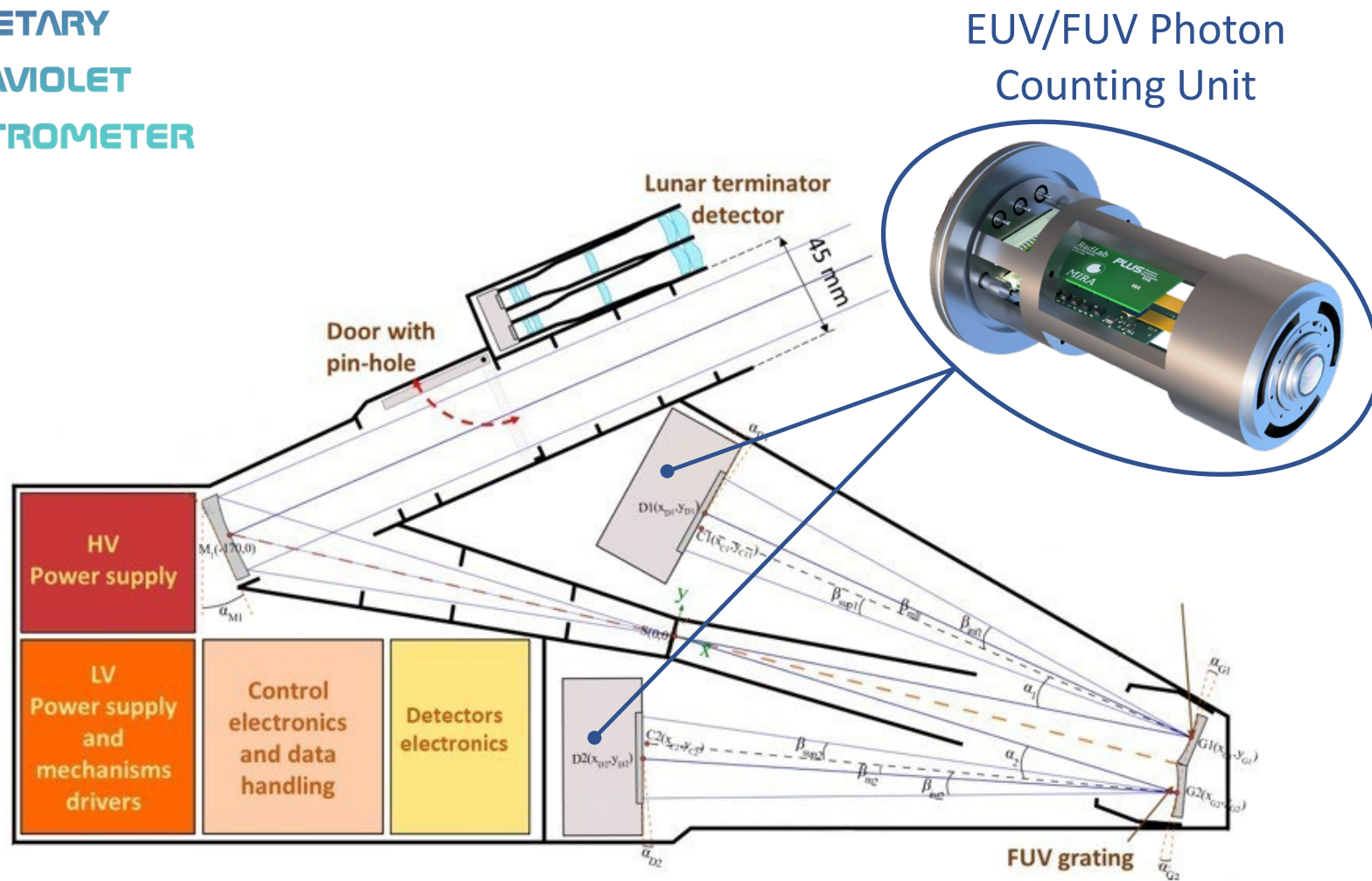


ESA. "Ultraviolet image shows the sun's intricate atmosphere"

# The PLANETARY Ultraviolet Spectrometer (PLUS) Project



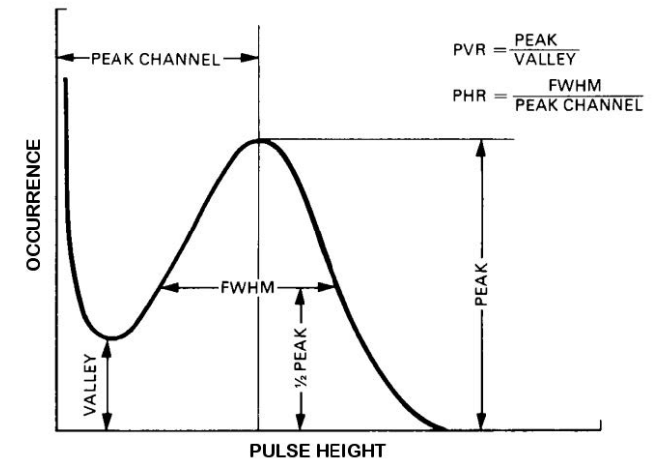
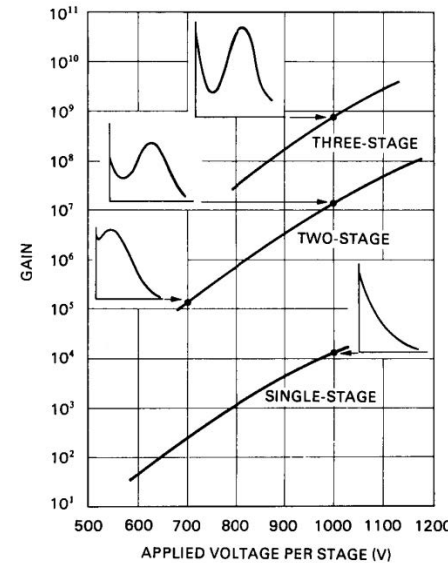
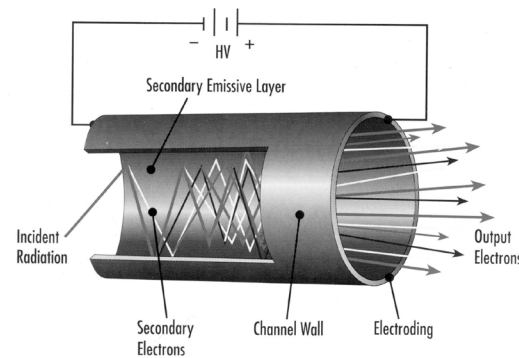
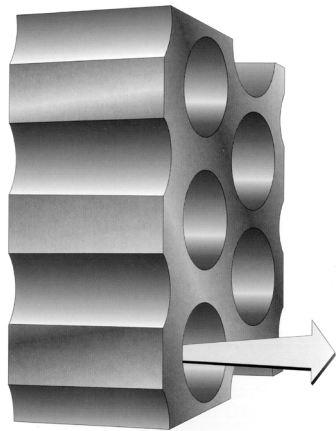
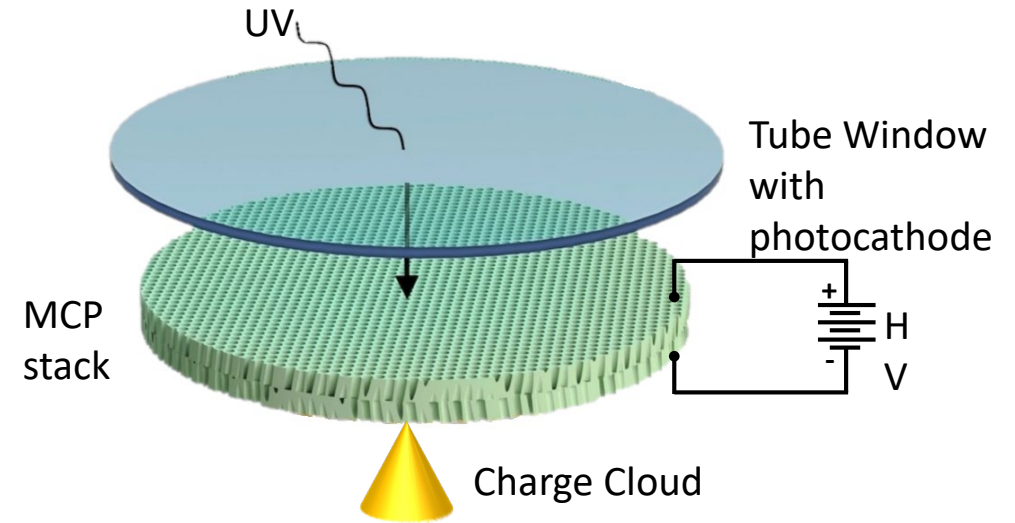
- Started in **2020**
- PoliMI, CNR, INAF
- Multichannel **FUV/EUV** imaging **spectrometer** for astronomical application
- Improved **detection limit**, **shorter observations** integration time, and in **dynamic range**
- EUV/FUV **MCP-based** photon counting unit for **events counting**





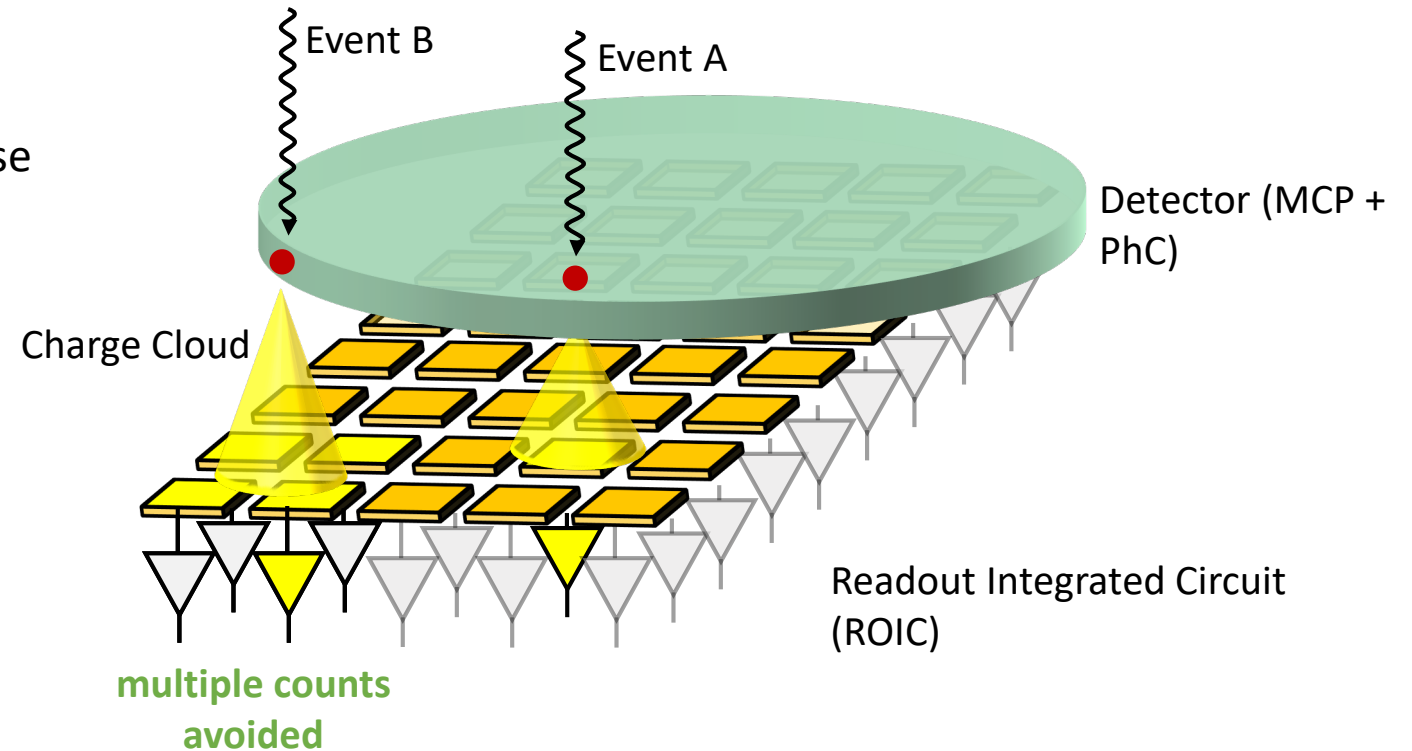
# Microchannel Plates Detectors (MCPs)

- **High time** resolution (down to 10 ps)
- **High spatial** resolution (down to 10  $\mu\text{m}$ )
- Large **format arrays** (> 1K x 1K pixels)
- Large **sensitive area** size (up to 20 cm)
- Low **dark current** (< 0.5 pA/cm<sup>2</sup> at HV = 1 kV)
- High out-of-band rejection (**solar blindness**)
- **Radiation** hardness and operation at **room temperature**



## Readout Integrated Circuit (ROIC):

- **Integrated 2D anode** array
- **Analog** and **Digital** circuits to perform pulse processing and events identification
- **Low noise** operation
- **High count rate** capability
- **Zero dead time**
- **Small pixel size**
- **Integrated charge sharing** correction



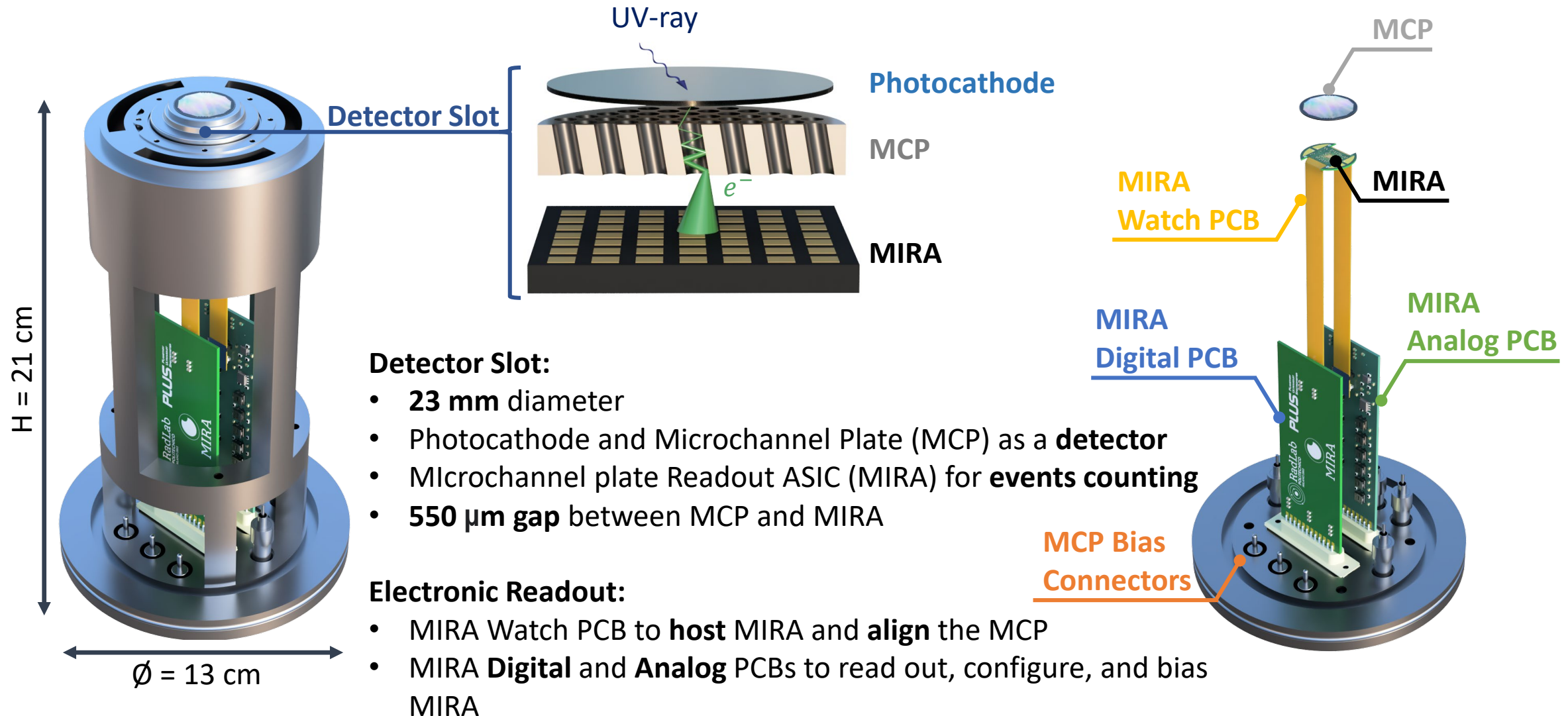
### Refs:

J Vallerga *et al* 2014 *JINST* 9 C05055

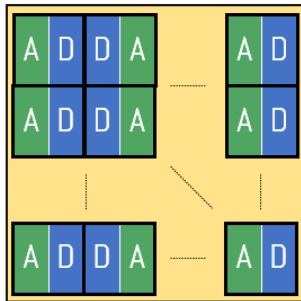
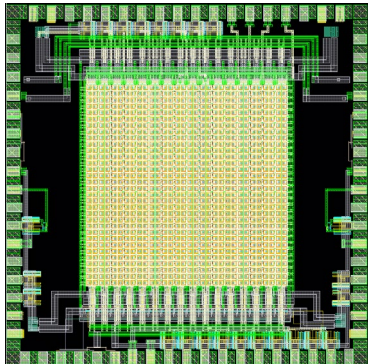
A.Harwit, wt al., Proc. SPIE, 91541N, 2014

**Goal of the project:** develop a custom-designed **ROIC** for the readout of **microchannel plates**

# The PLUS Photon Counting Unit

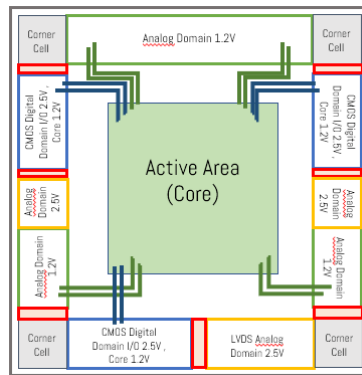


# MIRA Development Roadmap (3 years)



MIRA I:

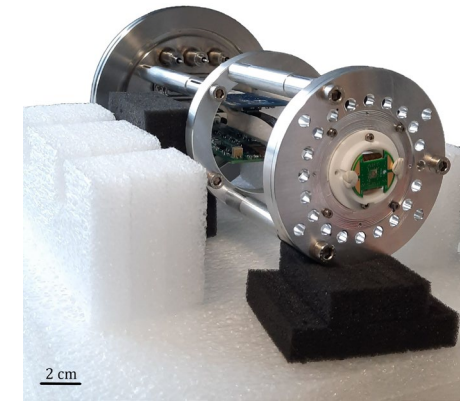
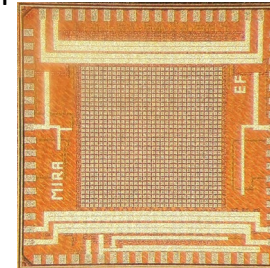
- Full-chip design
- MIRA I tape-out



2022

MIRA Acquisition system:

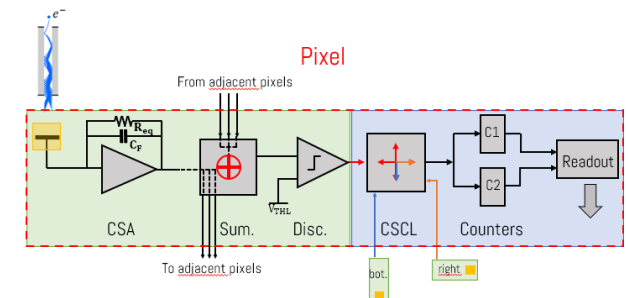
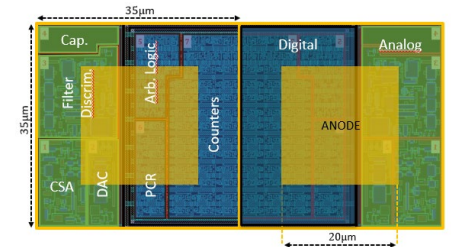
- GUI & RadLab setup & PLUS PCBs design
- MIRA I characterization
- MIRA II tape-out



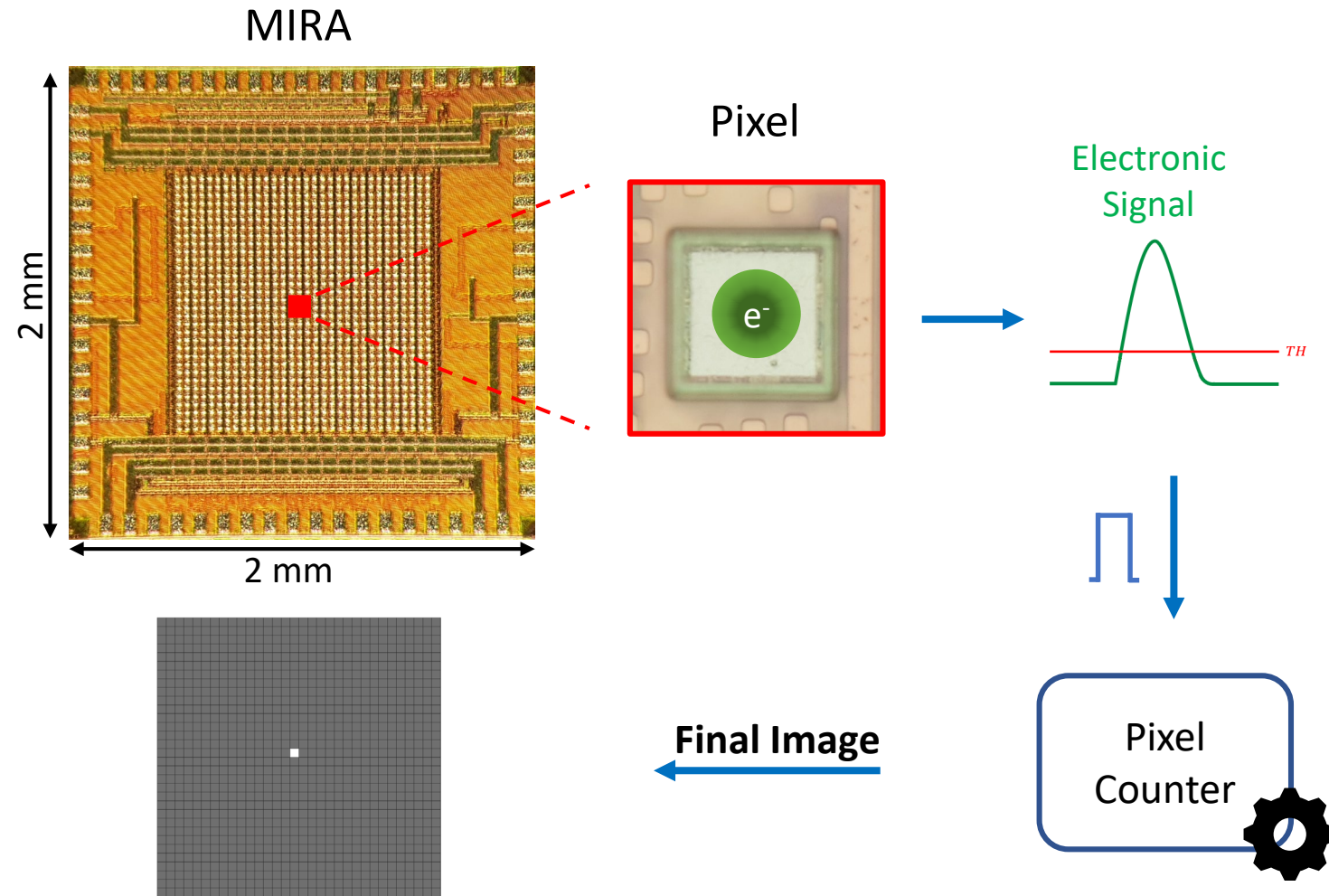
2020

MIRA I design started:

- Requirements
- Pixel schematic & layout design

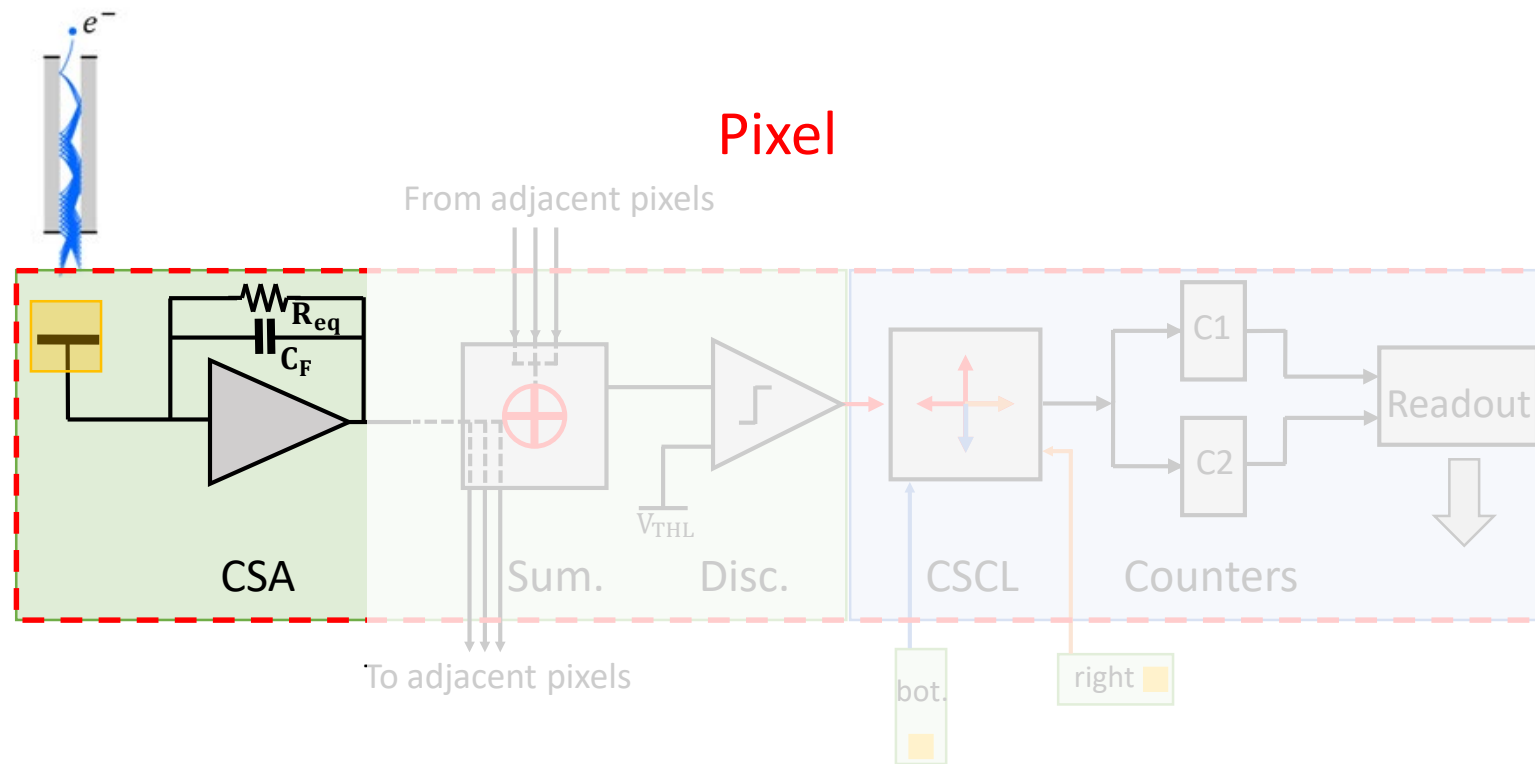




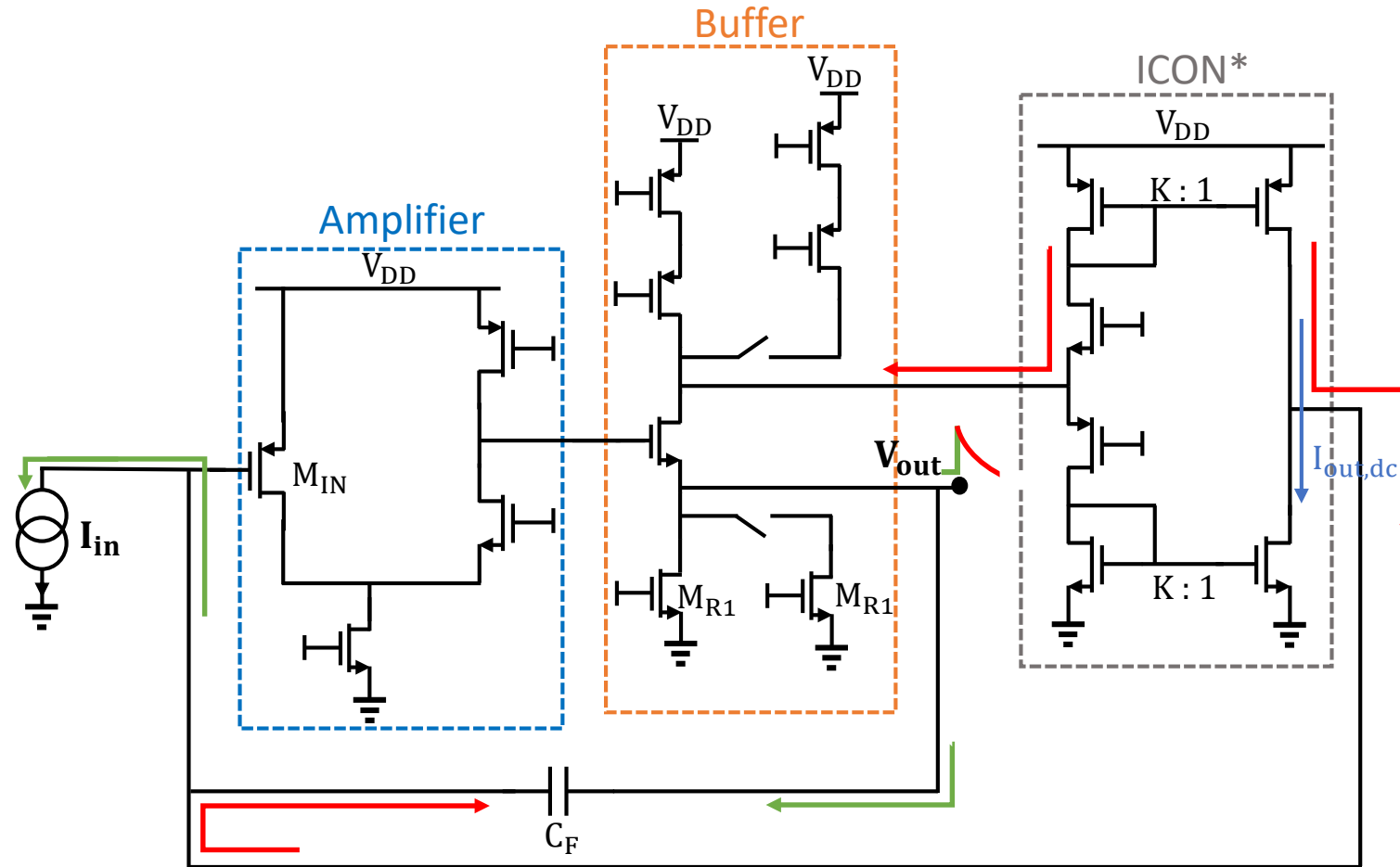


## MIRA Purpose and Specs:

- **Collect** the charge cloud with the integrated 2D anode array
- **35 $\mu\text{m}$ x35 $\mu\text{m}$**  pixel size
- **Low electronics noise (ENC = 20  $e^-_{\text{rms}}$ )** to operate the MCP at **low gain** and extend its lifetime in space.
- **Charge Sharing** Correction Logic to select a single pixel in charge shared events
- **Counting** capability up to **100kcounts/s/pixel**, zero dead time
- **32x32 pixels** prototype
- TSMC 65nm technology

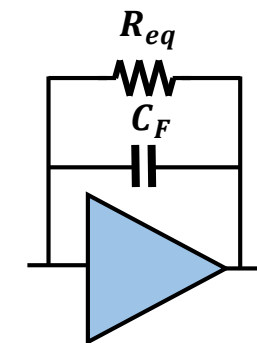


# MIRA Charge Sensitive Amplifier (CSA)



## MIRA CSA:

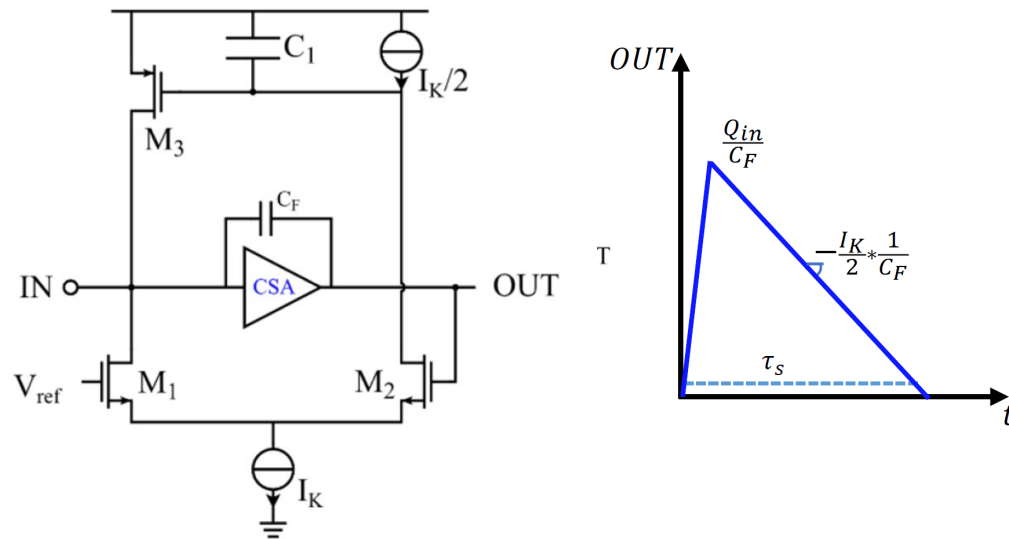
- **Folded Cascode Amplifier**
- **Buffer** → Selectable  $R_1$  for different shaping times: **Fast & Slow Mode**
- **ICON\*** → Large feedback resistance  
 $R_{eq} = R_1(1 + K)$  for  $C_F$  discharge



\* Refs:

- R. L. Chase, A. Hrisoho, J.-P. Richer: "8-channel CMOS preamplifier and shaper with adjustable peaking time and automatic pole-zero cancellation." Nucl. Instr. and Meth. A, vol. 409, 1998, p. 328–331.
- C. Fiorini and M. Porro, "Integrated RC cell for time-invariant shaping amplifiers", IEEE Trans. Nucl. Sci., Vol. 51, n°5, pp. 1953–1960, Oct 2004.

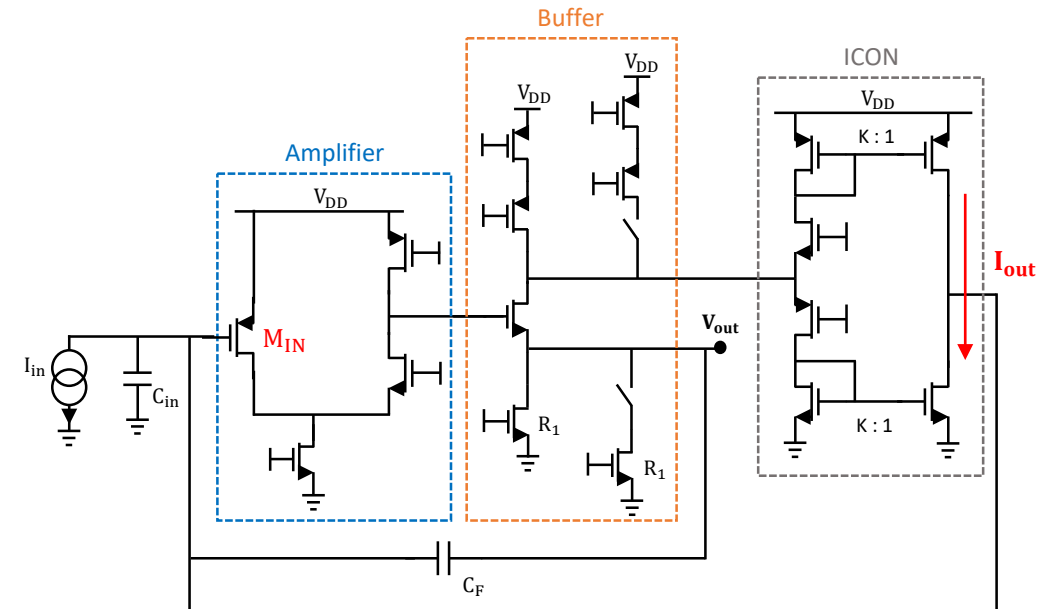
Krummenacher\*



- Shaping time  $\tau_s \propto \frac{1}{I_K}$
- Noise current source  $\propto I_K$
- Dependence between noise of  $I_K$  and shaping time

\*Ref: Krummenacher, Francois. "Pixel detectors with local intelligence: an IC designer point of view." Nuclear Instruments and Methods in Physics Research Section A **305.3** (1991): 527-532

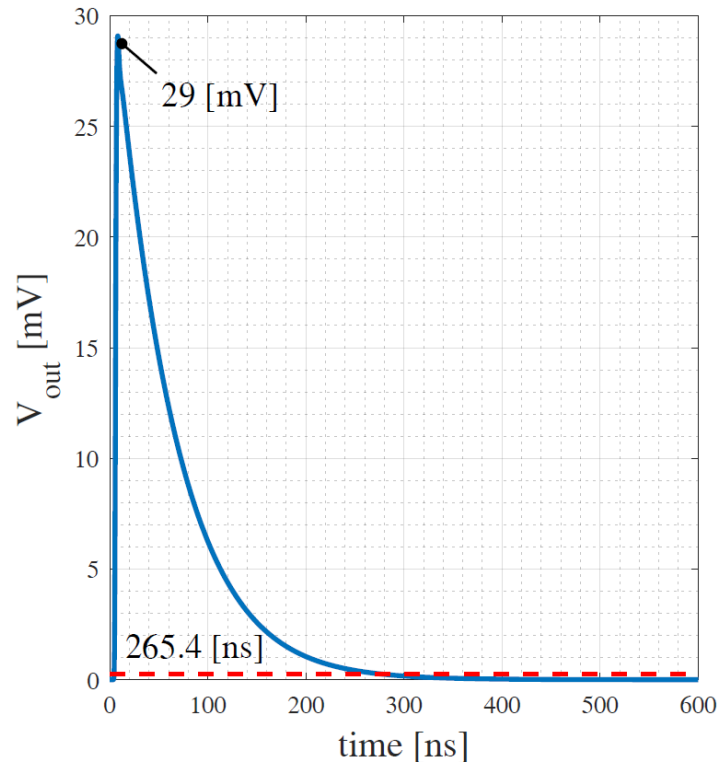
MIRA CSA



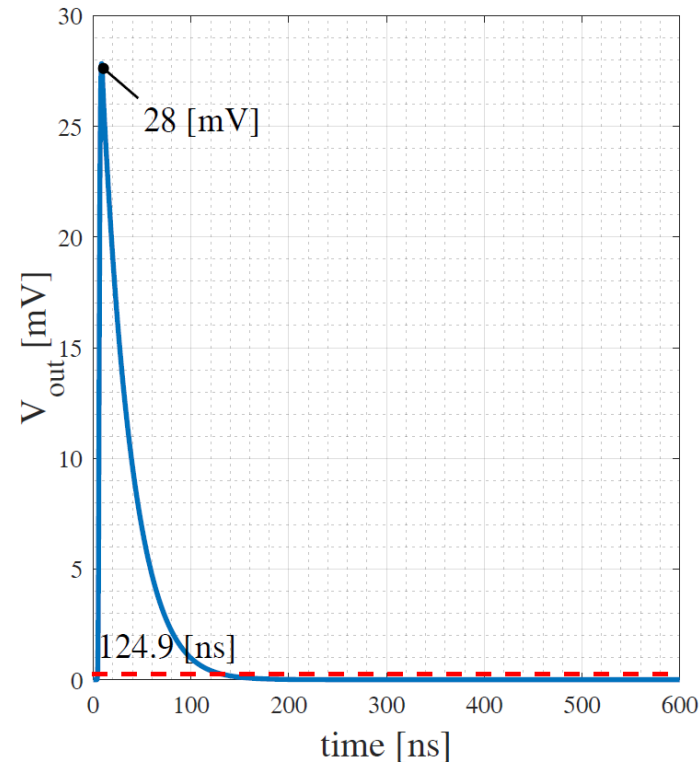
- Main noise current source at the input  $\propto I_{out}$
- Shaping time  $\tau_s \propto KR_1 C_f$
- No dependence between noise of  $I_{out}$  and shaping time
- Buffer and left-branch ICON noise sources demagnified by a factor  $K^2 \rightarrow$  negligible



## Slow Mode



## Fast Mode



$$Q_{in,MAX} = 4000 e^-$$

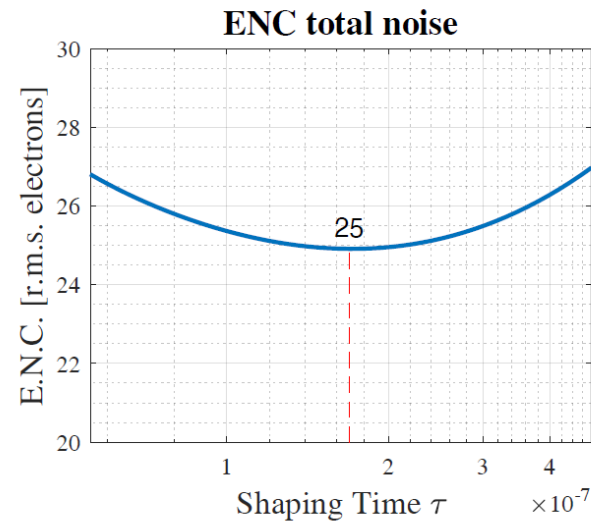
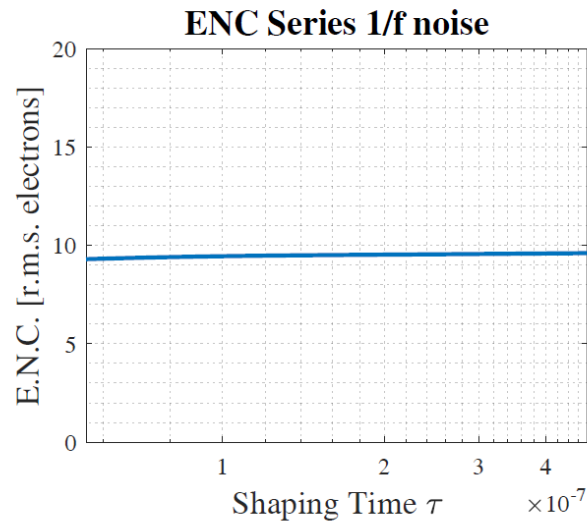
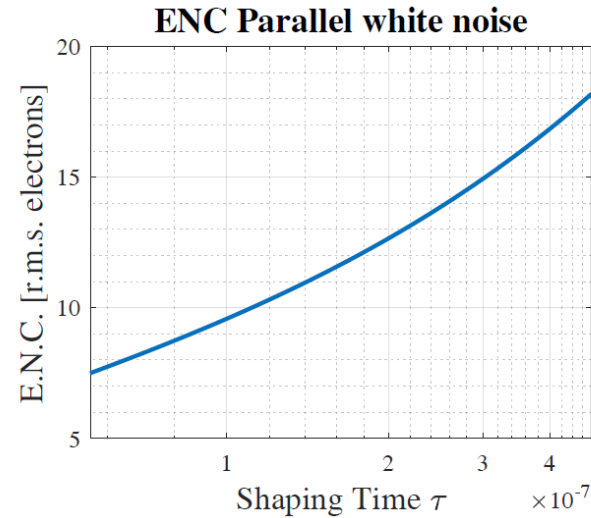
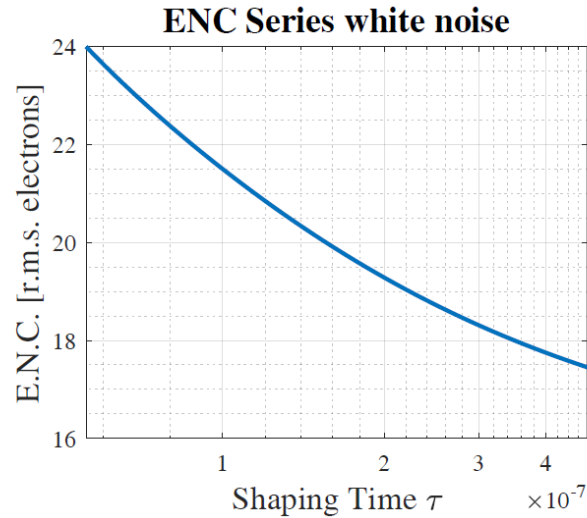
## Slow Mode:

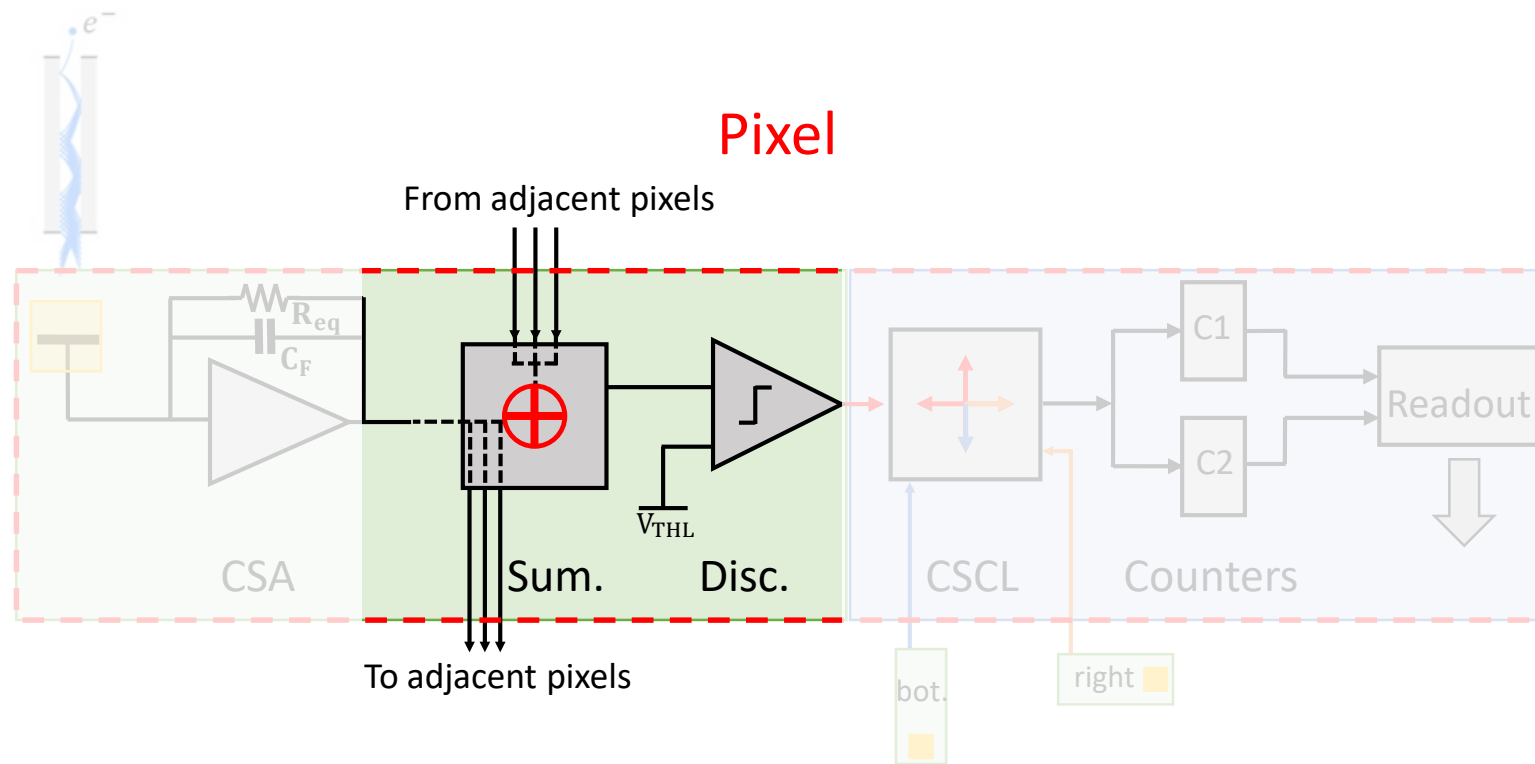
- $t_{width|1\%peak} = 265 \text{ ns}$
- $V_{peak} = 29 \text{ mV}$
- $Q_{in} = 1000 e^-$
- $\sigma_{n,vout} = 835 \mu V_{rms}$
- $ENC_{CSA} = 27 e^-_{rms}$

## Fast Mode:

- $t_{width|1\%peak} = 125 \text{ ns}$
- $V_{peak} = 28 \text{ mV}$
- $Q_{in} = 1000 e^-$
- $\sigma_{n,vout} = 835 \mu V_{rms}$
- $ENC_{CSA} = 27 e^-_{rms}$

# Noise contributions - Simulations



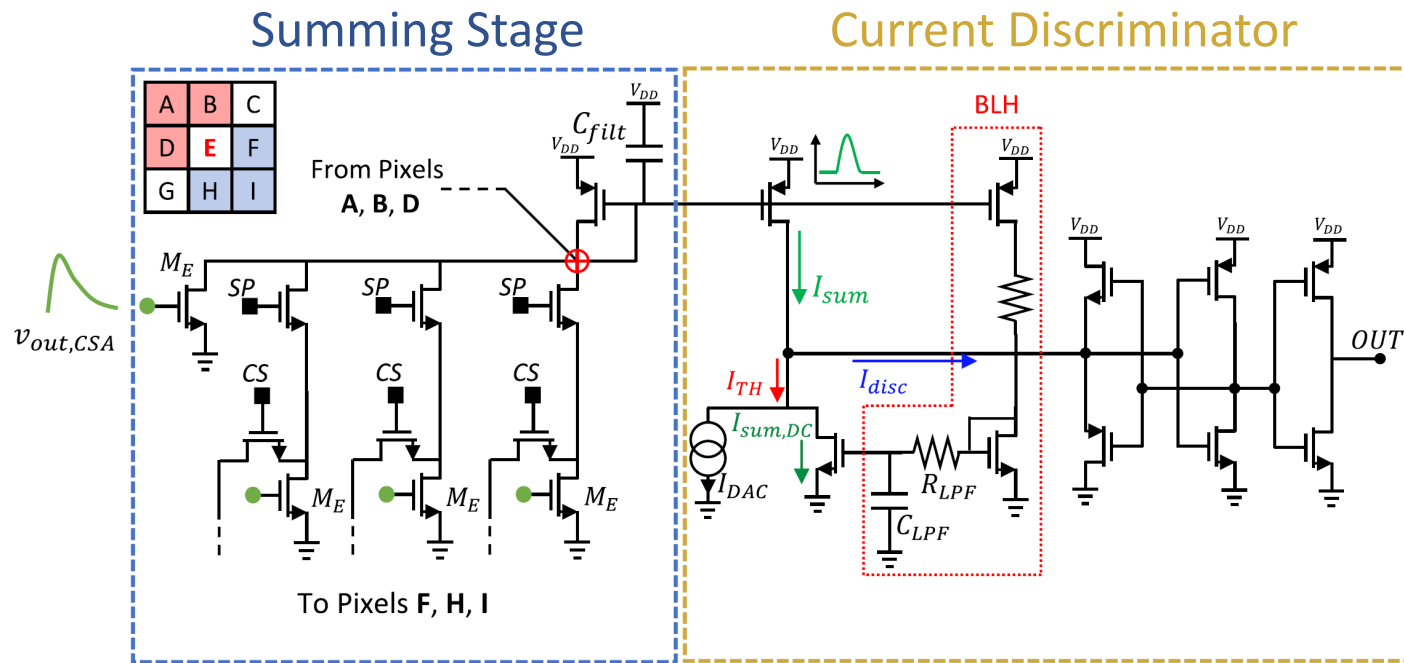


# MIRA Summing Stage and Discriminator

A	B	C
D	E	F
G	H	I

\*

**Pixel E**



## MIRA Summing Stage:

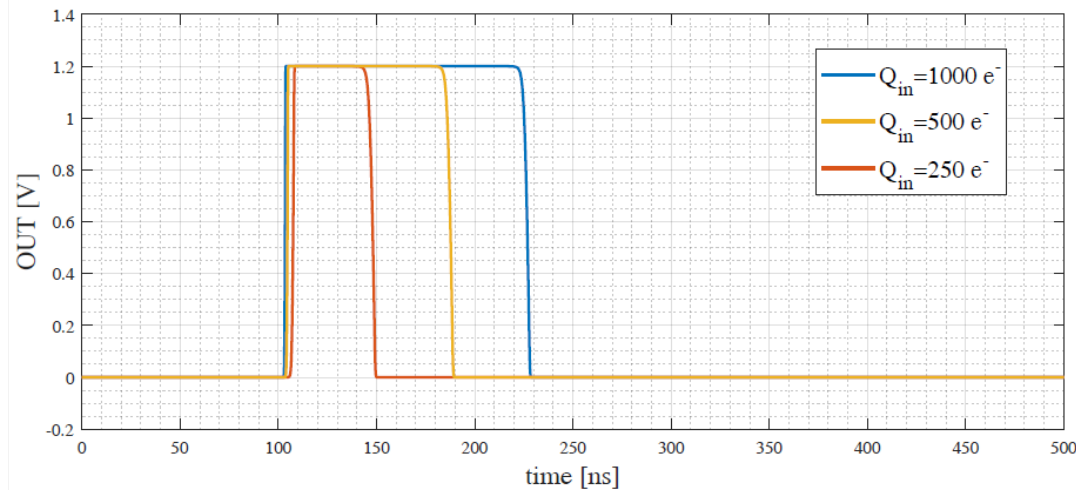
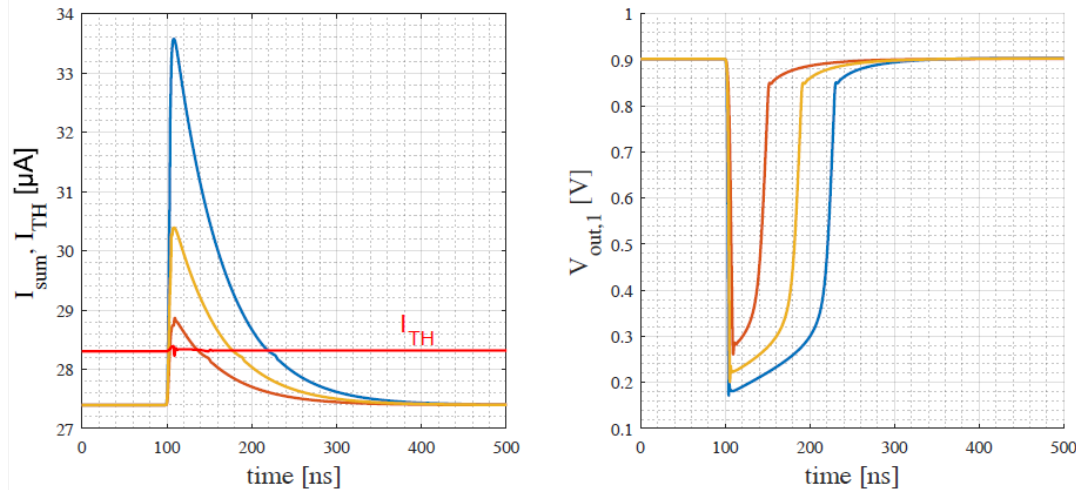
- **Charge Summing Mode (CS)** → Signal sum from adjacent pixels\*
- **Single Pixel Mode (SP)** → Gain × 4
- **Low-pass Filtering** on the sum signal →  $C_{LPF}$

## MIRA Current Discriminator:

- **Tunable Threshold** → 4-bit DAC + 1 Sign bit
- **DC Feedback (Baseline Holder)** → Improves compensation of mismatches

\*Ref: R. Ballabriga et al: "The Medipix3 prototype, a pixel readout chip working in single photon counting mode with improved spectrometric performance." IEEE Trans. Nucl. Sci., vol. 54, no. 5, 2007, p. 1824–1829.



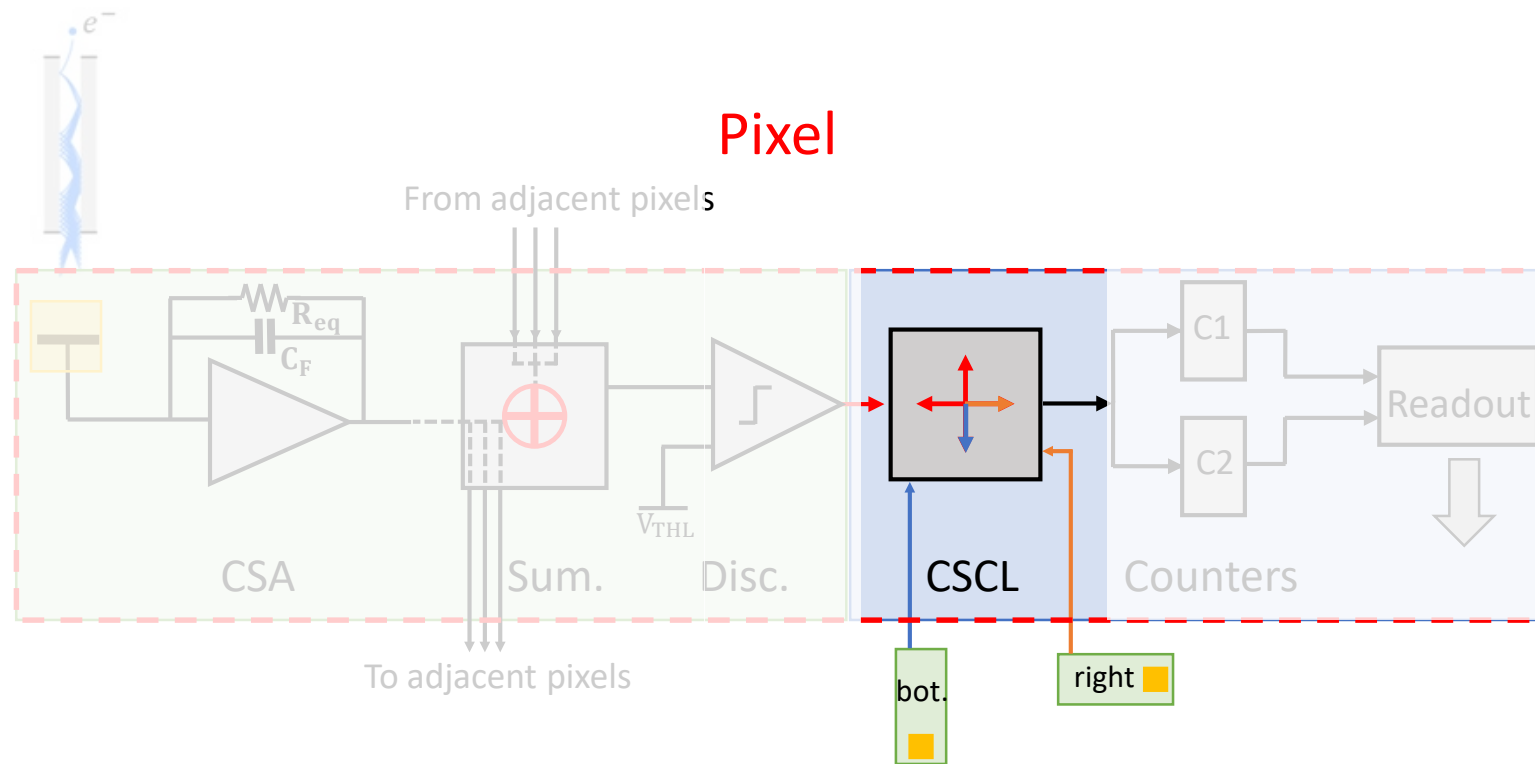


- **ToT strategy: higher the charge, the faster the pulse arrival time and the longer its duration**

Example:

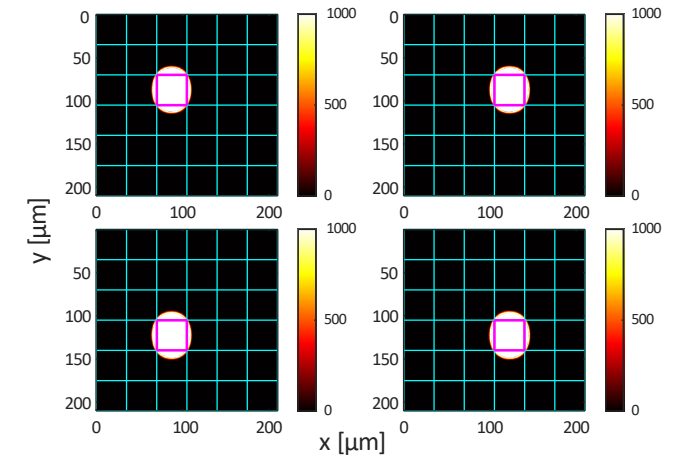
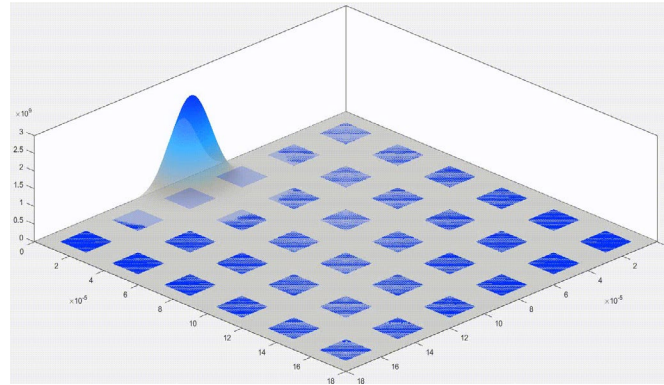
$Q_{in} [e^-]$	Rising Edge Arrival Time [ns]	Falling Edge Arrival Time [ns]
1000	3.4	126.25
500	4.1	88.9
250	7.6	47.5

- **Noise after 2<sup>nd</sup> stage:**
  - **ENC** = 17  $e_{rms}^-$  in SP and Slow Mode
  - **ENC** = 18  $e_{rms}^-$  in SP and Fast Mode



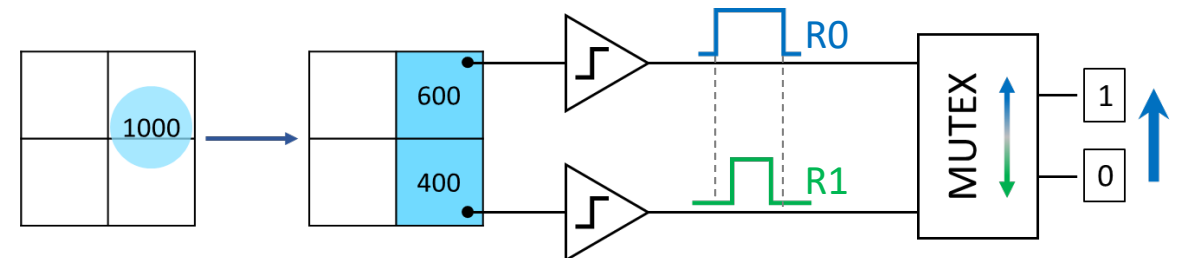
## Simulation Model:

- **Electrons cloud:**  $Q_{MCP} = 4000e^-$ ,  $\sigma_x = 7\mu\text{m}$ ,  $\sigma_y = 9\mu\text{m}$
- Multiple **counts** and a degraded **spatial resolution**
- **Anode size:**  $20\mu\text{m}$



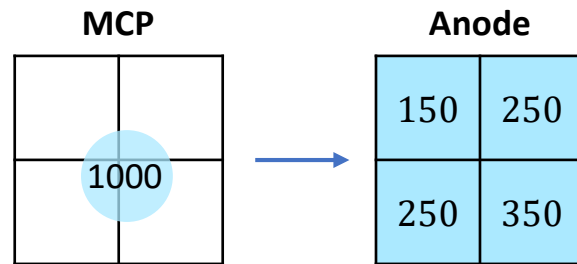
## Charge Sharing Correction:

- **Highest** amount of charge identification  $\rightarrow$  MUTEX
- Mutex is based on an **SR latch**
- Several comparisons inside a **cluster** of 2x2 pixels
- **Two** modalities of operations Mode2 and Mode3
- Multiple **counts** avoided and **spatial resolution** recovered

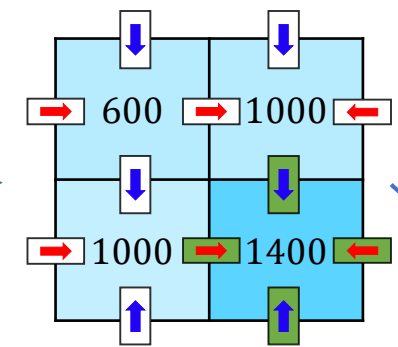


## Mode2

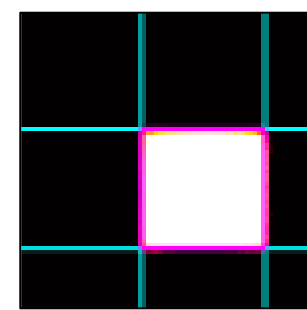
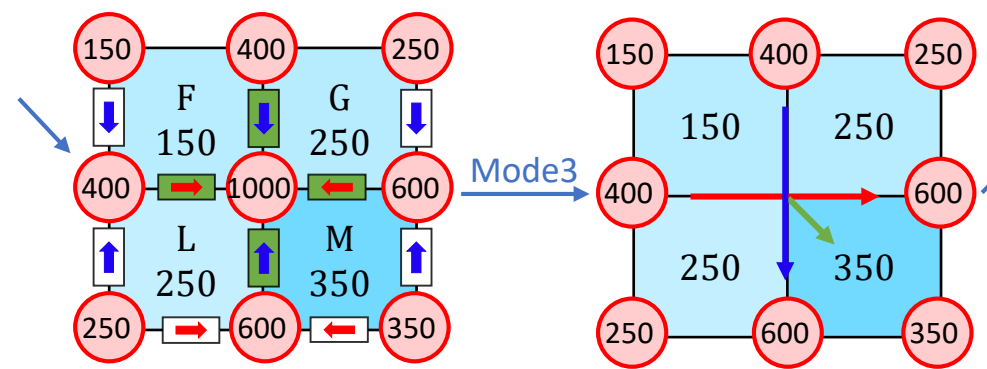
- Filter Stage in **Single Pixel** mode (SP)
- Horizontal and vertical **comparisons** with the charge collected by each anode



## Mode2



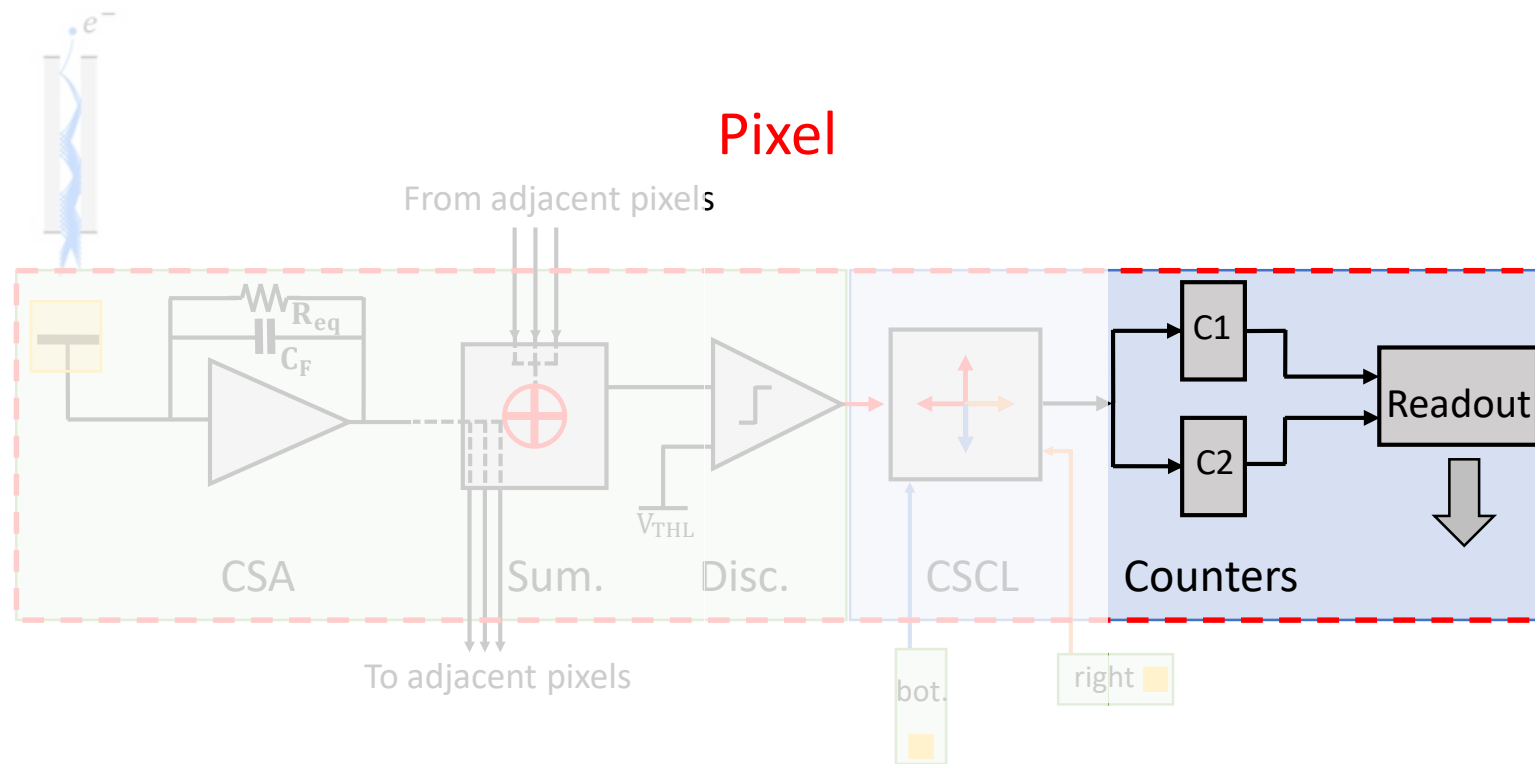
## Mode3



## Mode3

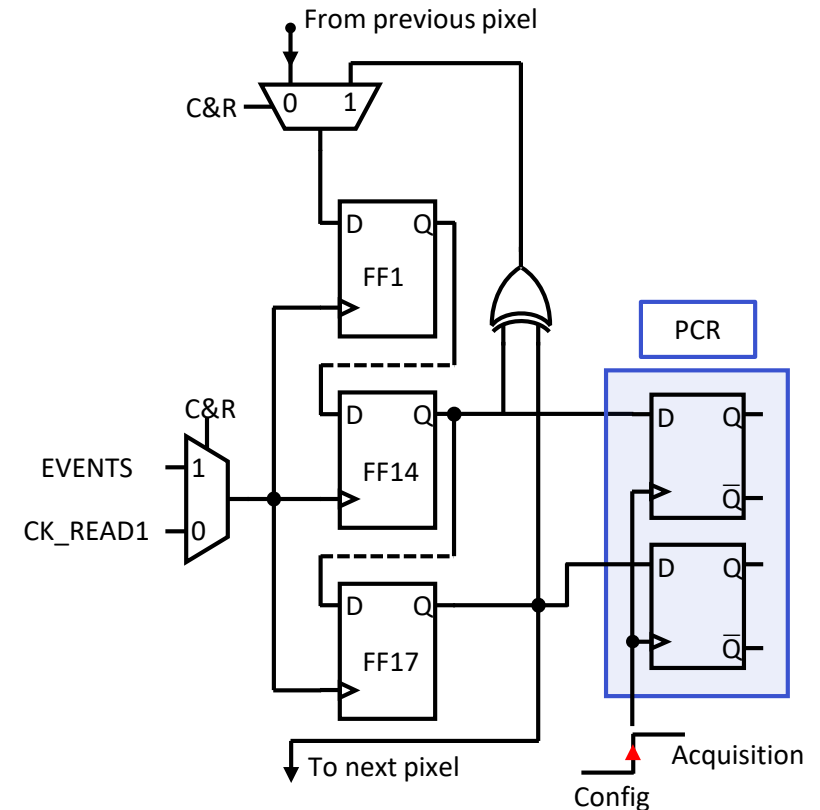
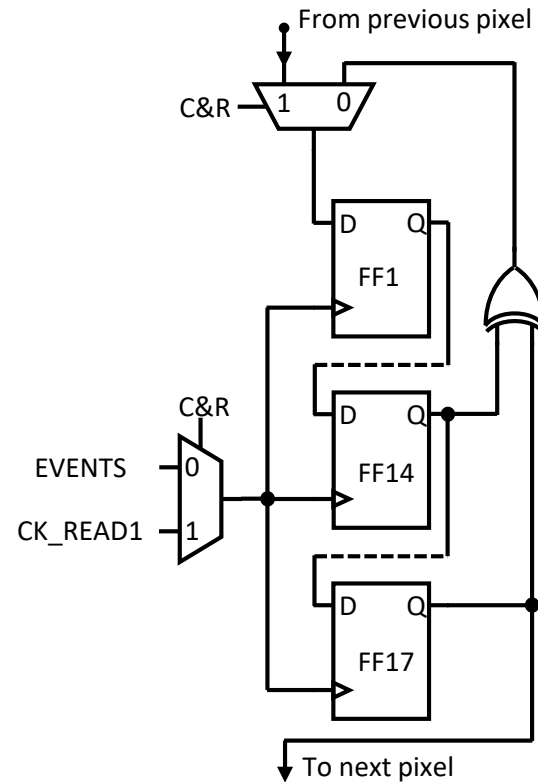
- Filter Stage in **Charge Summing** Mode (CS)
- **Cluster** identified by summing node
- **Comparisons** made on all pixels in the cluster (including diagonal)



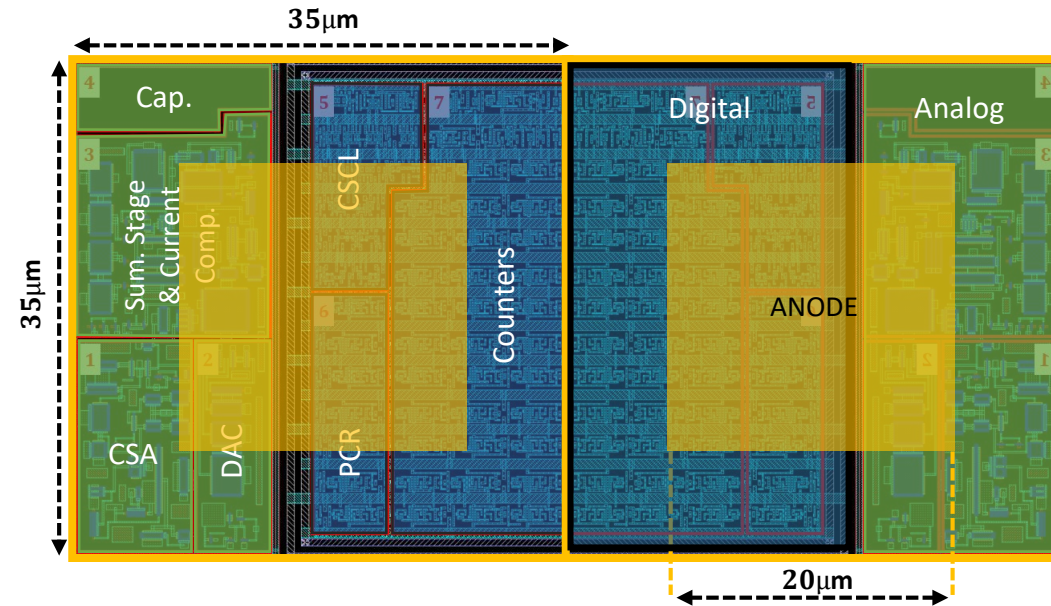
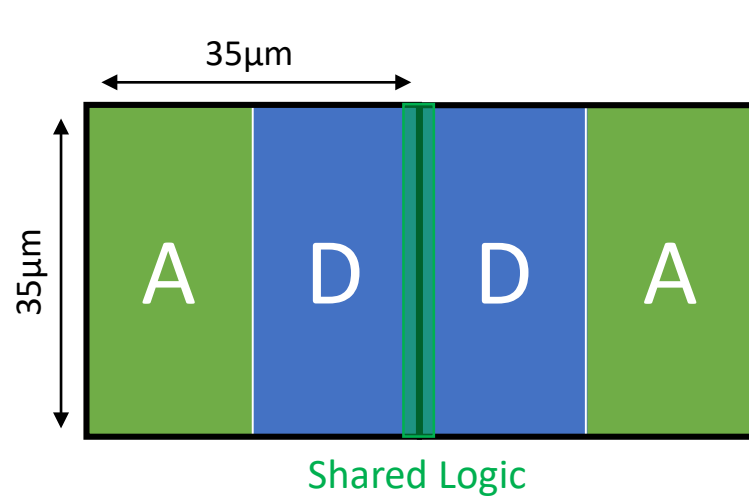


## Pixel readout stage:

- Two **17-bit counters**
- Implemented as **Linear Feedback Shift Register (LFSR)**
- LFSR acts as a counter or shift register
- **Continuous** counting and reading phases to have **zero dead time**
- **7-bit Pixel Configuration Register (PCR)** to program the pixel

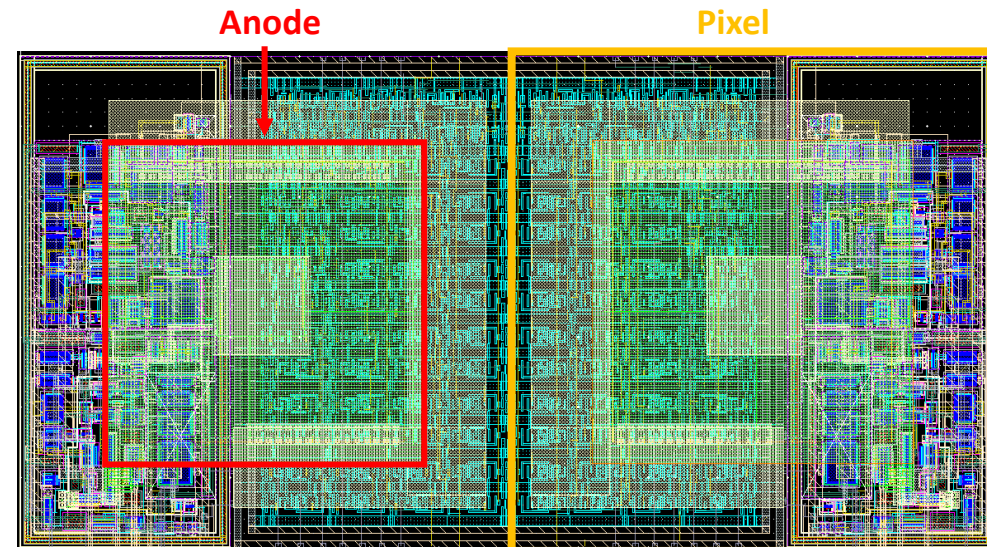


# The SuperPixel - Layout



## The SuperPixel:

- **Two** mirrored pixels with adjacent digital parts
- **35x35 μm<sup>2</sup>** pixel size with **20x20 μm<sup>2</sup>** anode size
- **Half-analog** and **half-digital** pixel
- **Fully-custom** design for **analog** part, **RTL** design and synthesis for **digital** part

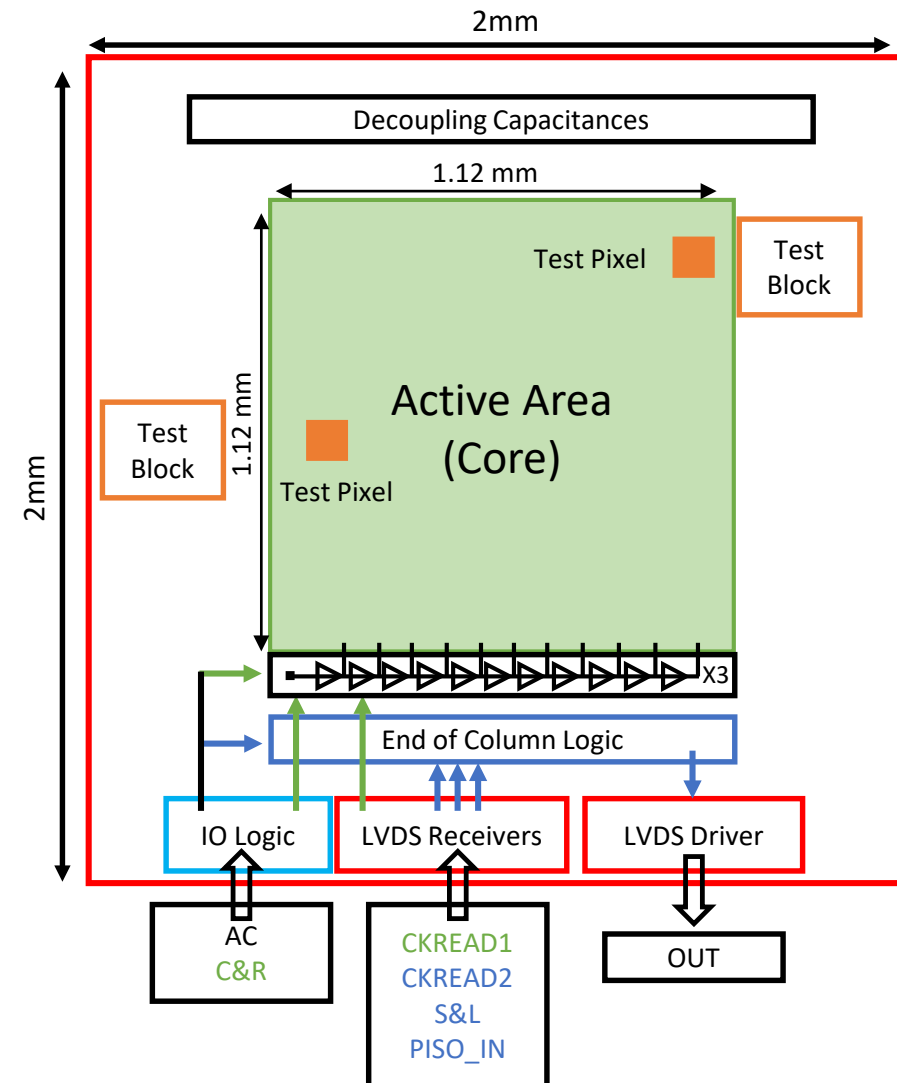


## MIRA first prototype:

- 2x2 mm<sup>2</sup> chip area
- 1.12x1.12 mm<sup>2</sup> **active** area
- **Two** test pixels

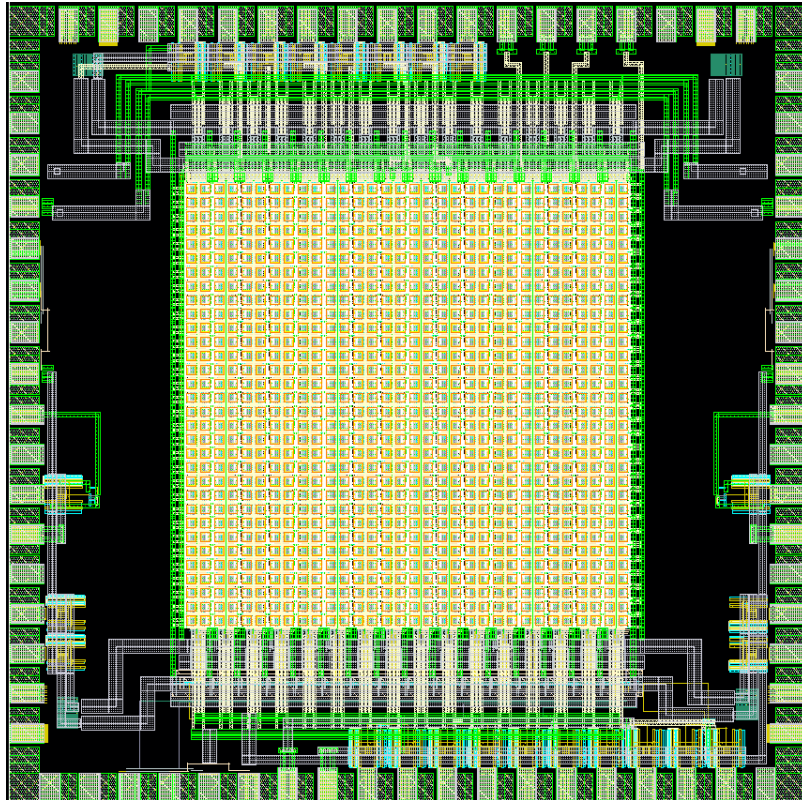
## Periphery & Power Domains:

- **Column drivers** for column bus lines
- **EoC** logic and **I/O** drivers
- **LVDS** driver and receivers
- **Two** test blocks
- **Decoupling** capacitances
- **Analog and Digital** power domains
- **Supplies isolation**
- **CUP** structure

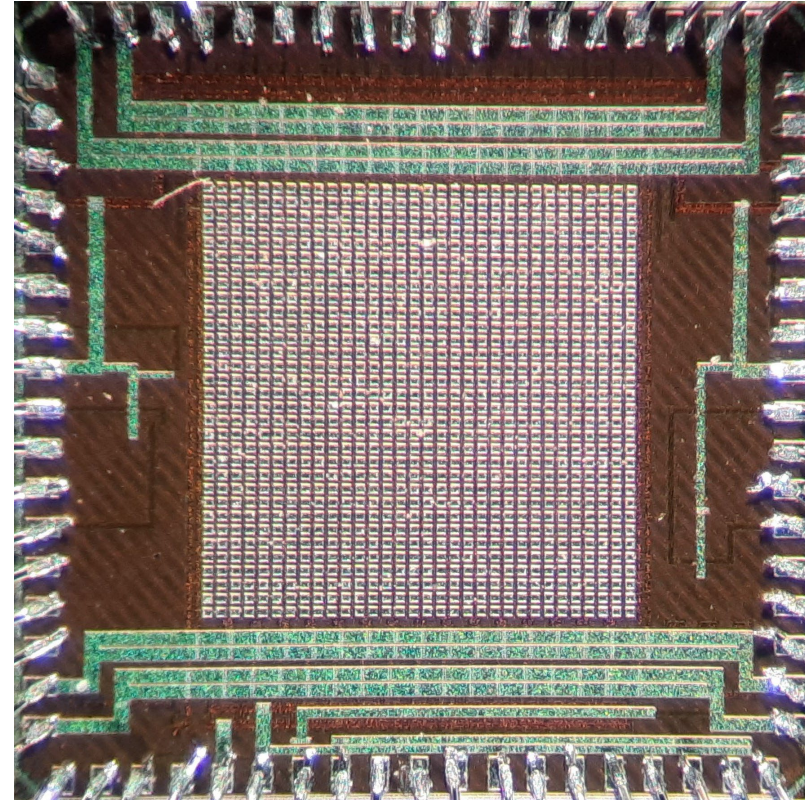




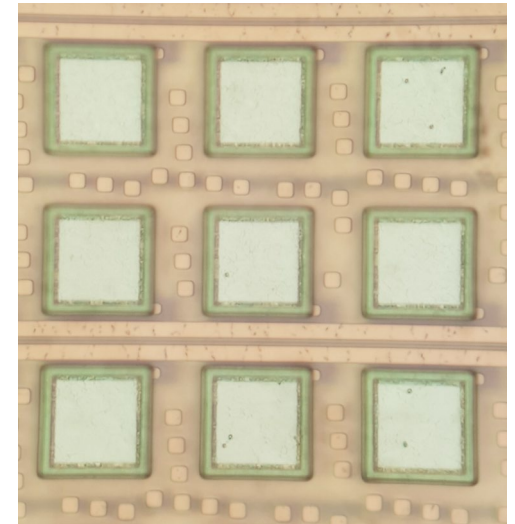
Layout



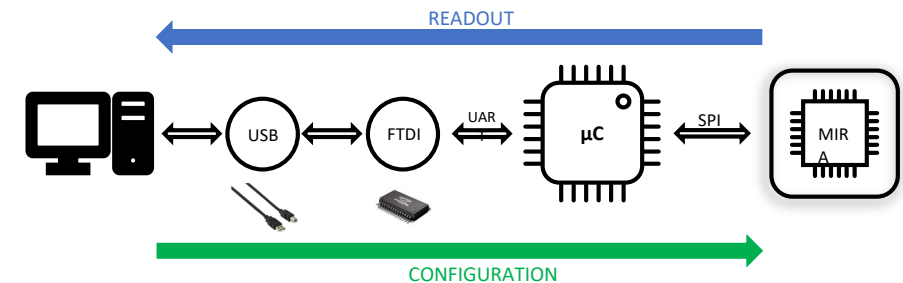
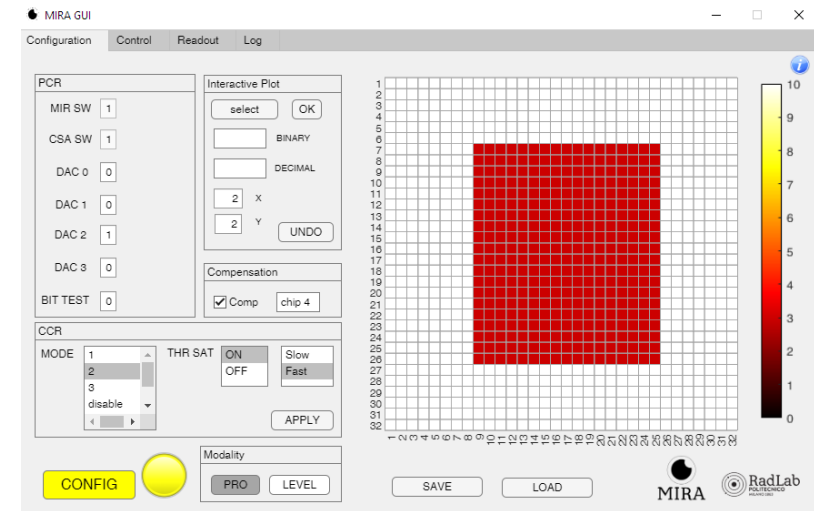
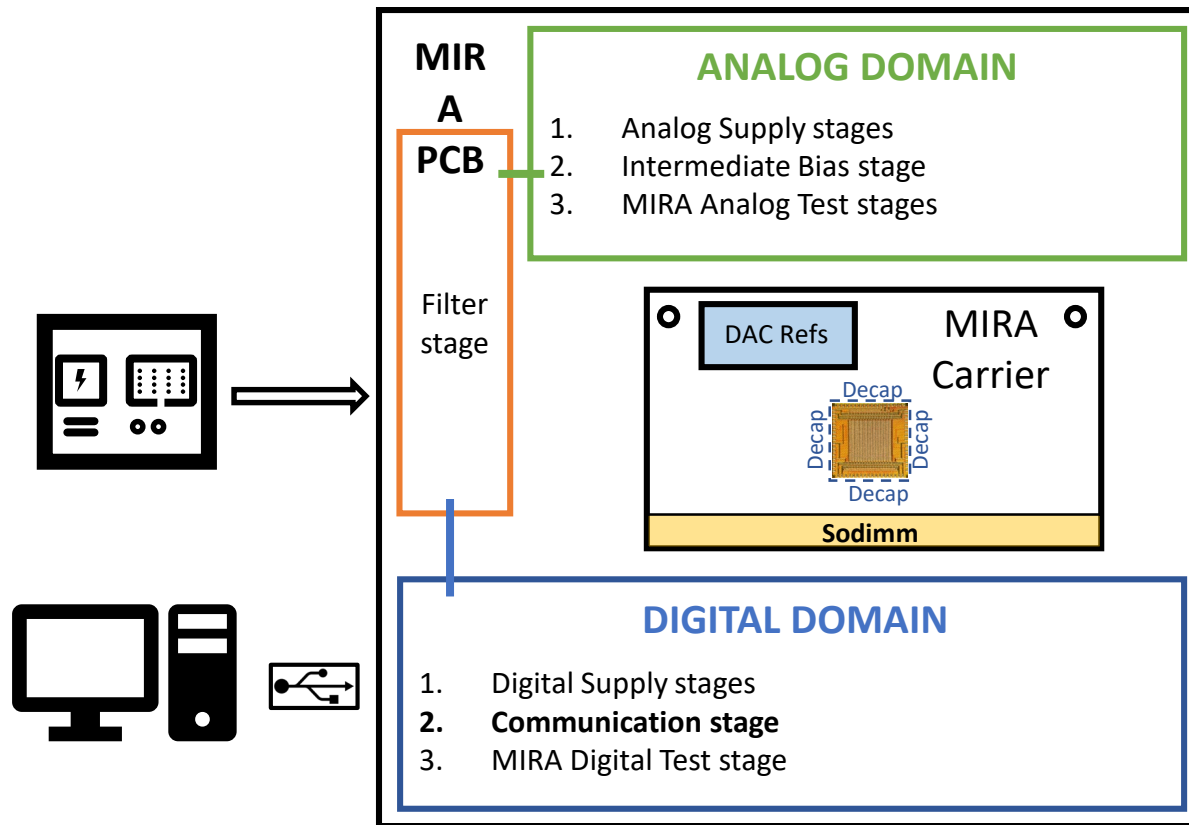
Microscope Image



Anodes



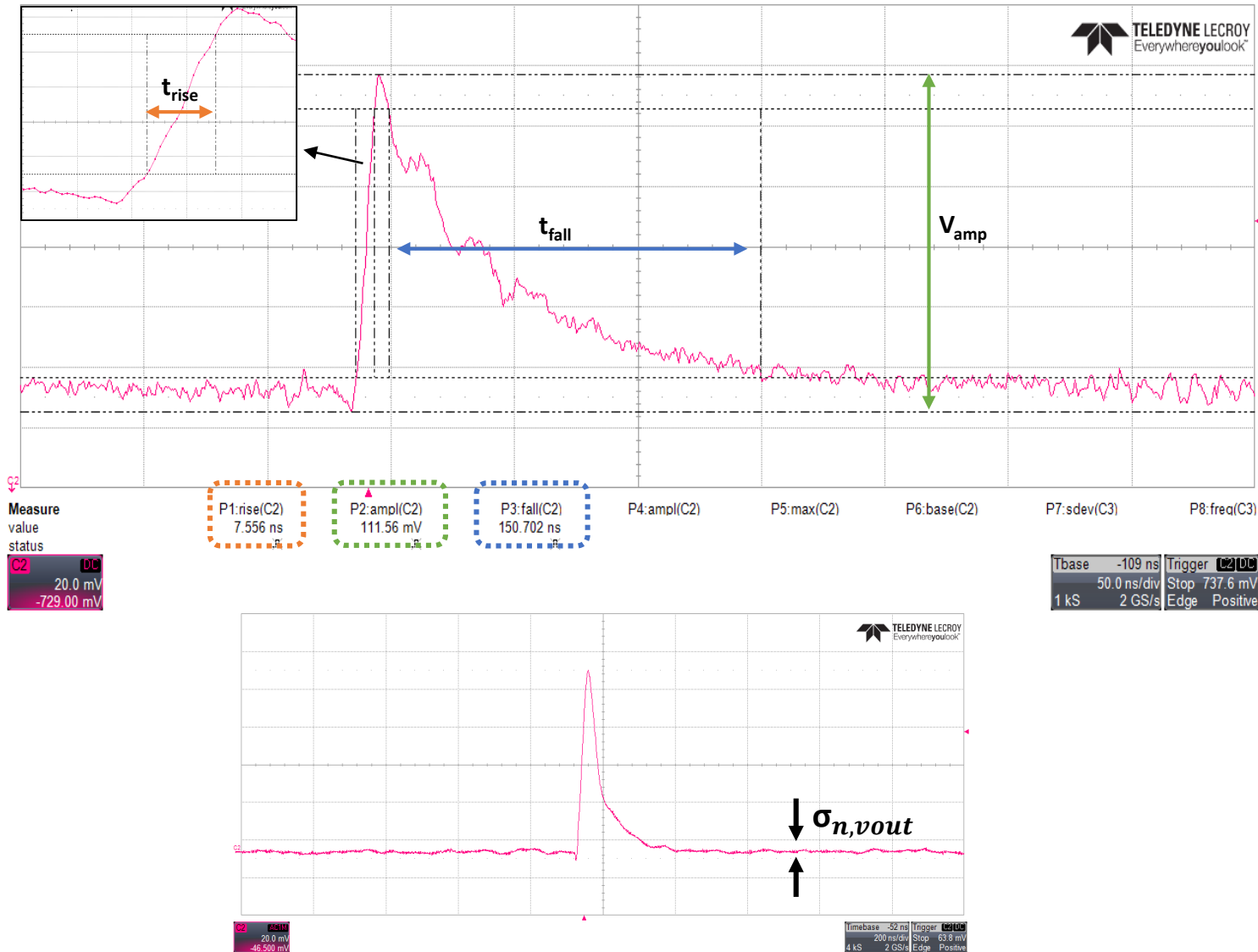
# MIRA Acquisition System



- MIRA PCB to **supply, configure, read** MIRA and monitor the test pixels
- MIRA Carrier to **host MIRA**
- Communication with an external PC through **USB 2.0**
- MATLAB-based **GUI** to show and arrange the **acquired and configuration data** of the MIRA ASIC



# MIRA I CSA Transient Response - Measurements



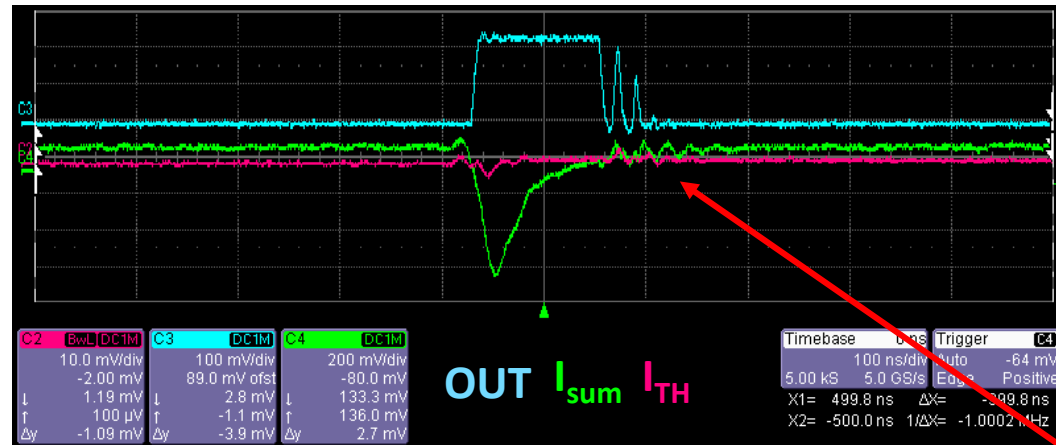
With active probe:

- **Slow Mode**
- $t_{rise} = 7 \text{ ns}$  ,  $t_{fall} = 150 \text{ ns}$
- $t_{width}|_{1\%peak} = 261 \text{ ns}$
- $V_{amp} = 112 \text{ mV} \rightarrow Q_{in} = 4000 e^-$

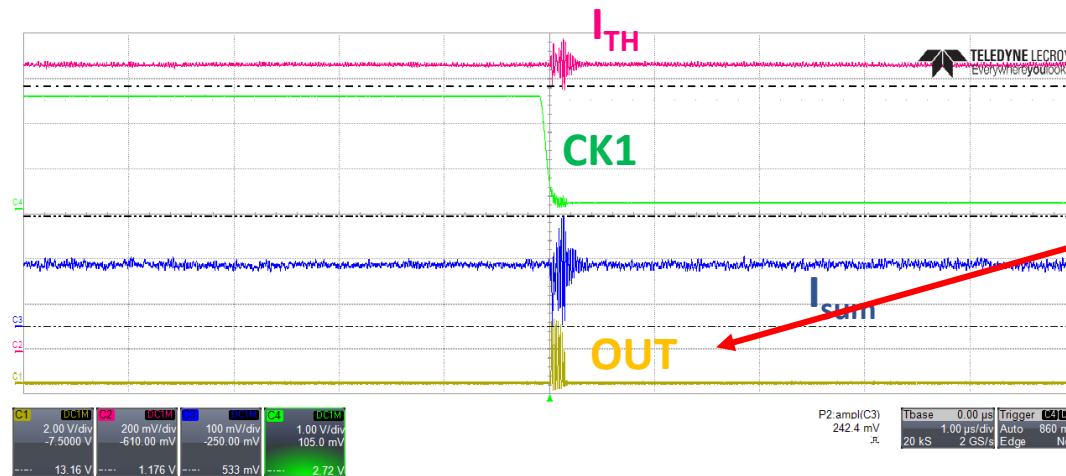
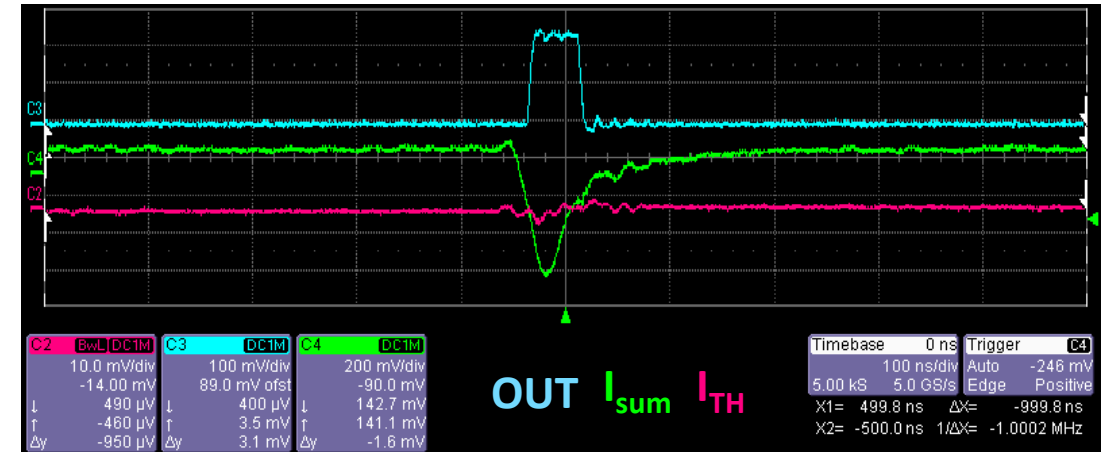
With SMA connection:

- $t_{rise} = 22 \text{ ns}$
- $\sigma_{n,vout} = 750 \mu V_{rms}$
- $ENC_{CSA} = 27 e^-_{rms}$

### Low Threshold (just above noise)



### High Threshold



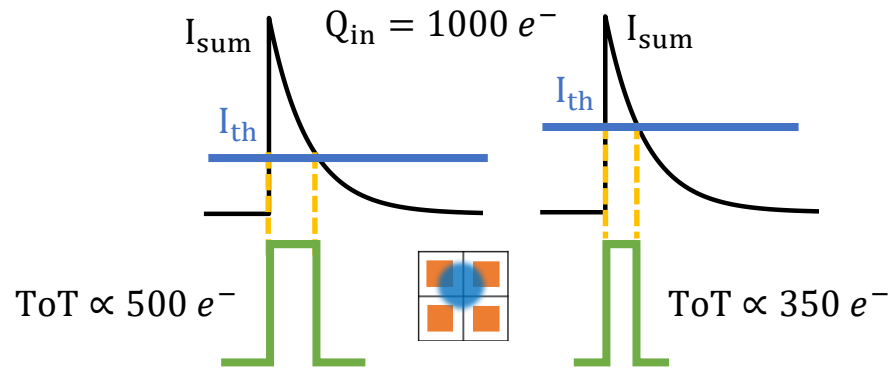
- Self-triggers in low-threshold operations
- Clock (CK1) coupling causing false counts
- High-threshold operation to trigger single events
- Threshold **lower limit**: 500 e<sup>-</sup>
- ENC = 20 e<sup>-</sup><sub>rms</sub>

OUT: current comparator output

# Charge Sharing Correction Logic - Results

## Test Setup:

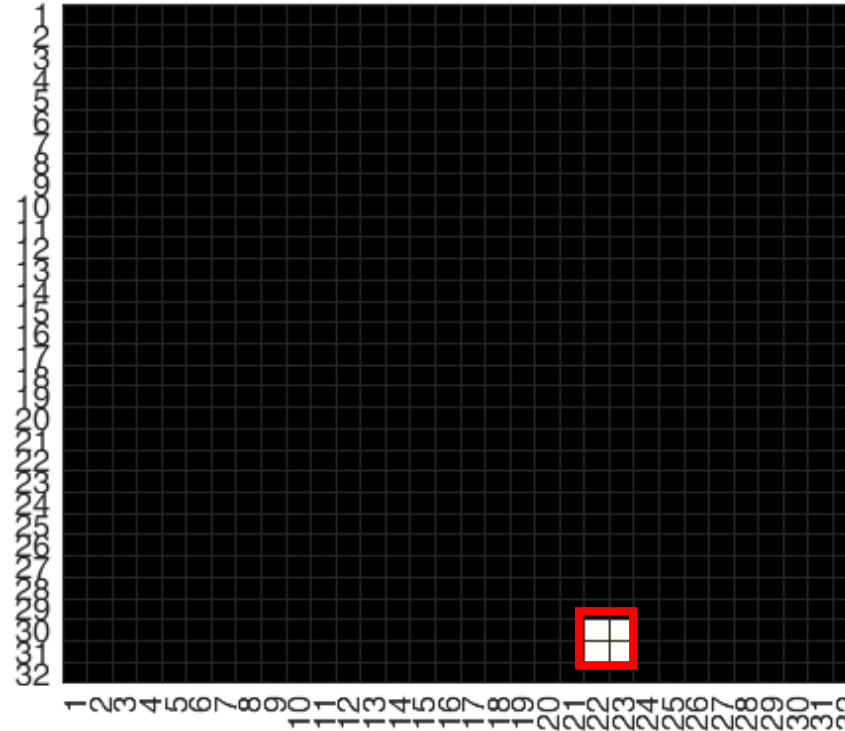
- Each pixel stimulated with **same** test signal ( $Q_{in,eq} = 1000 e^-$ )
- **Different** pulse ToTs obtained by programming the cluster pixels with **different thresholds**



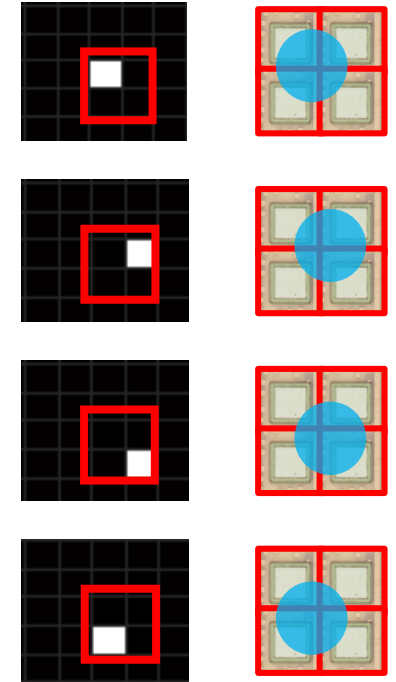
## Results:

- Only the pixel with the **highest charge** is counting
- **MIRA CSCL** works as expected
- Multiple pixel **counts** avoided

## No Correction



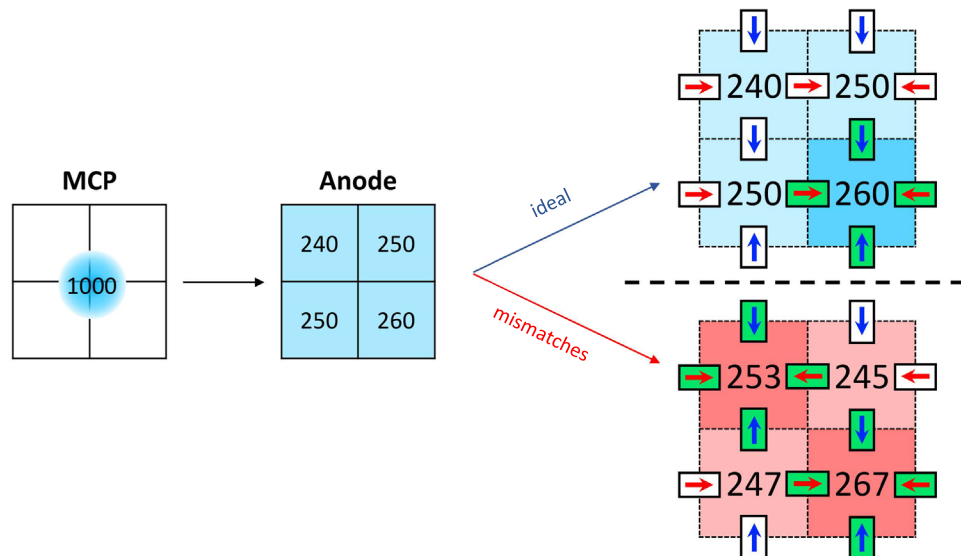
## Mode2



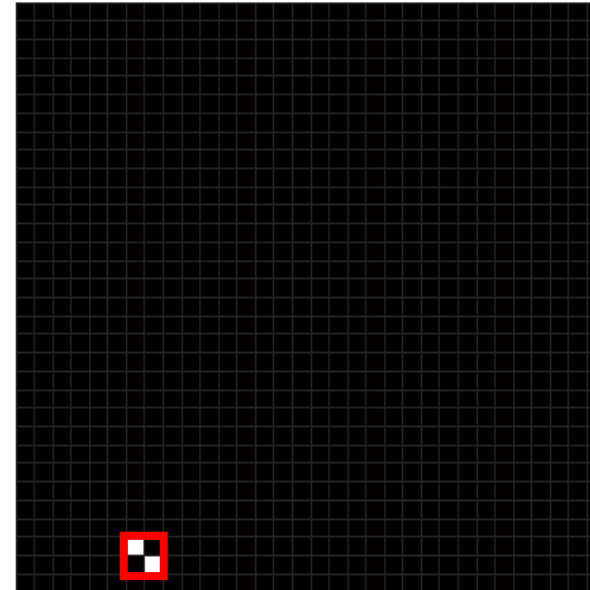
# Mode2 vs Mode3

## Diagonal double counting:

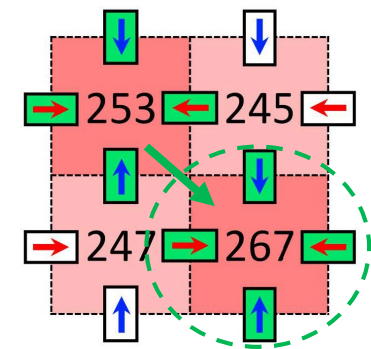
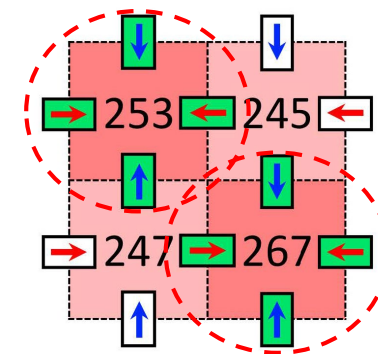
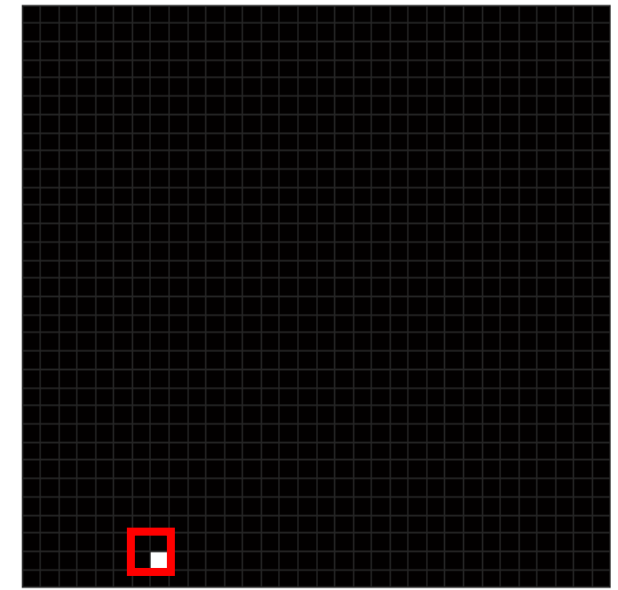
- A **diagonal double counting** may occur in **Mode 2** from a **charge cloud** almost equally shared in the cluster, and **pixels mismatches**
- It results in two diagonally-placed pixels with **longer ToTs**
- **Mode3** solves it performing diagonal comparisons



Mode2

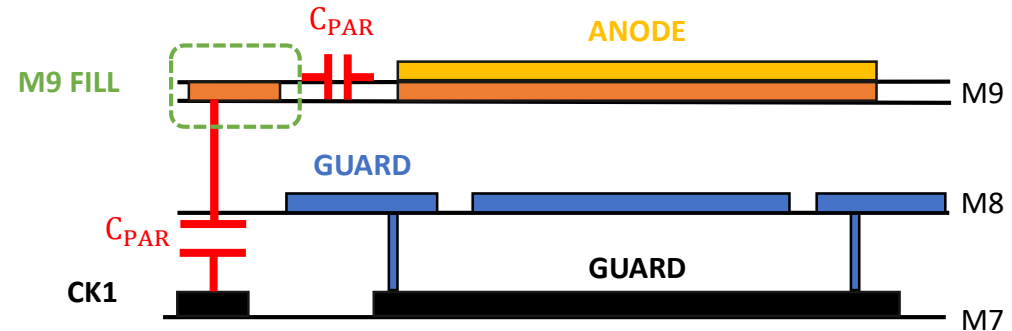
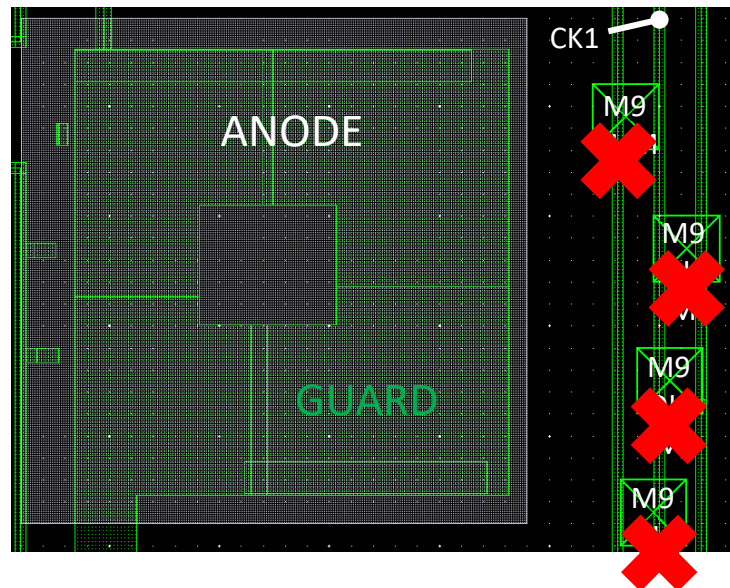


Mode3



## Clock coupling:

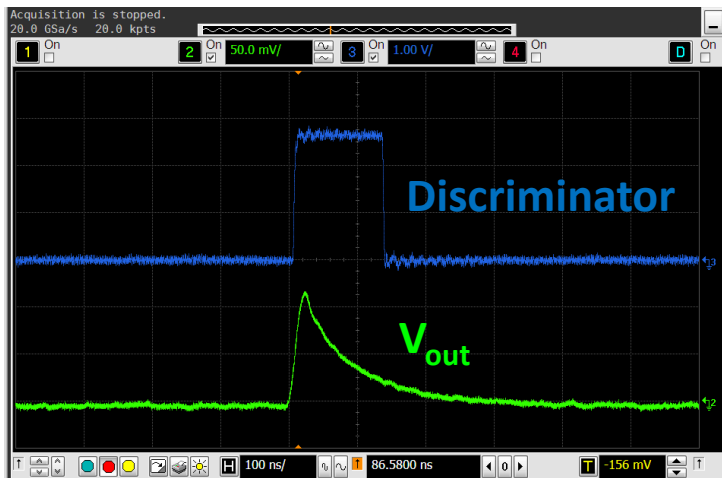
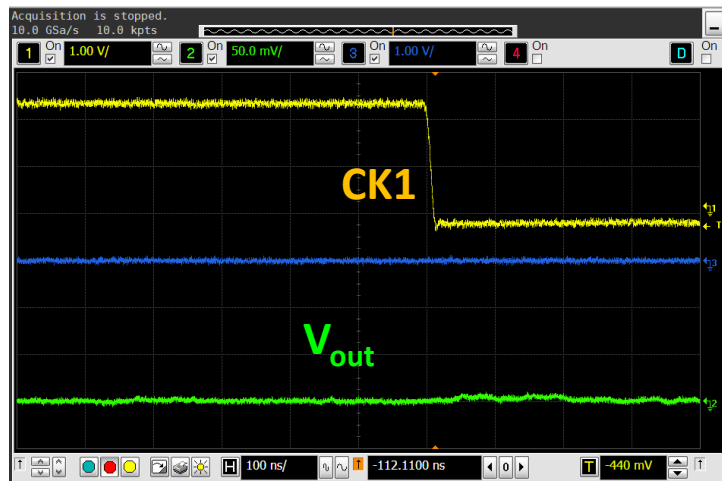
- Parasitic coupling between **clock lines** and **Anode** pad
- Coupling induced by **metal dummies patterns** in M9 (foundry)



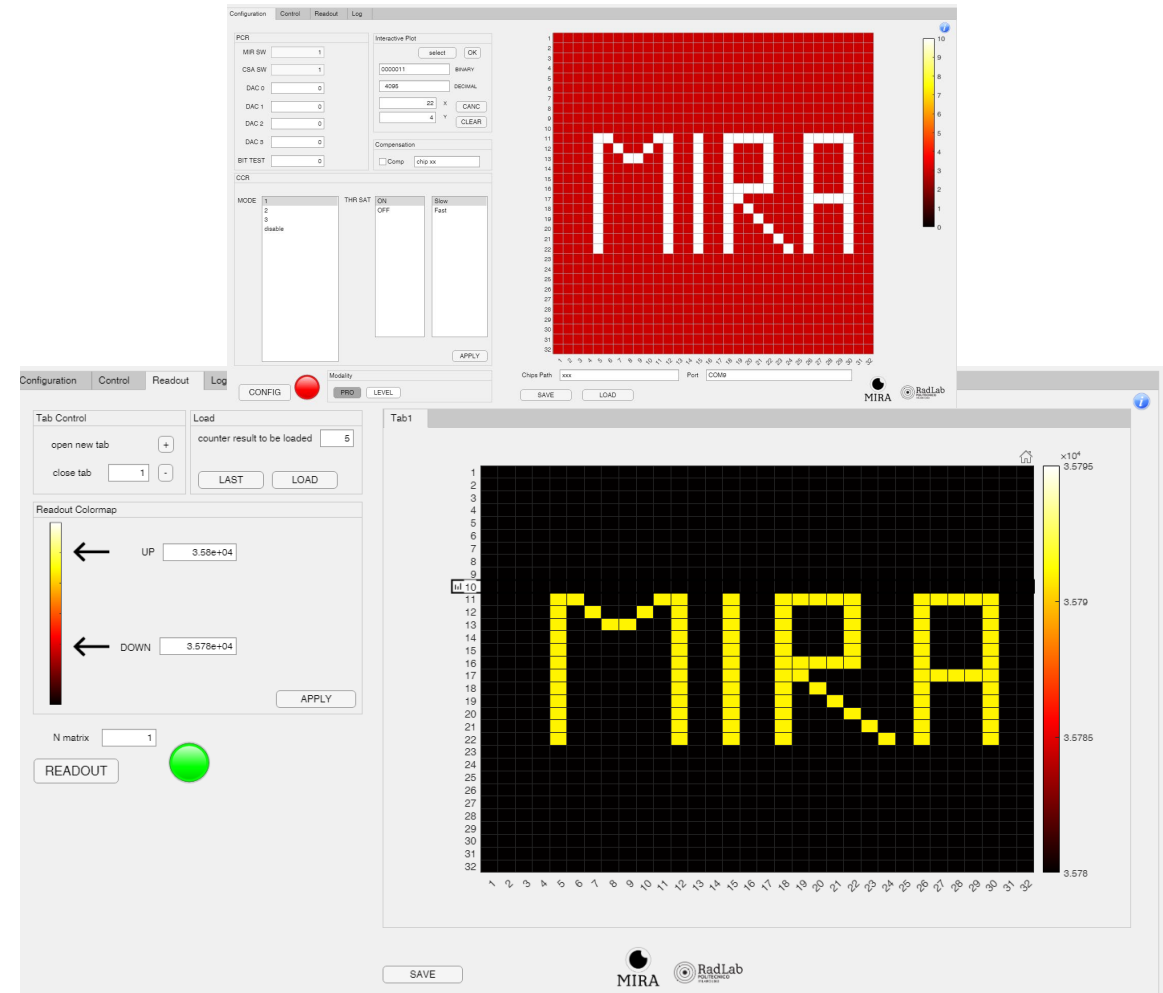
## Further improvements:

- **Elimination of self-trigger** due to digital pickup on analog pulse
- **Improvement of clock distribution** (configuration and readout issues, not discussed here)

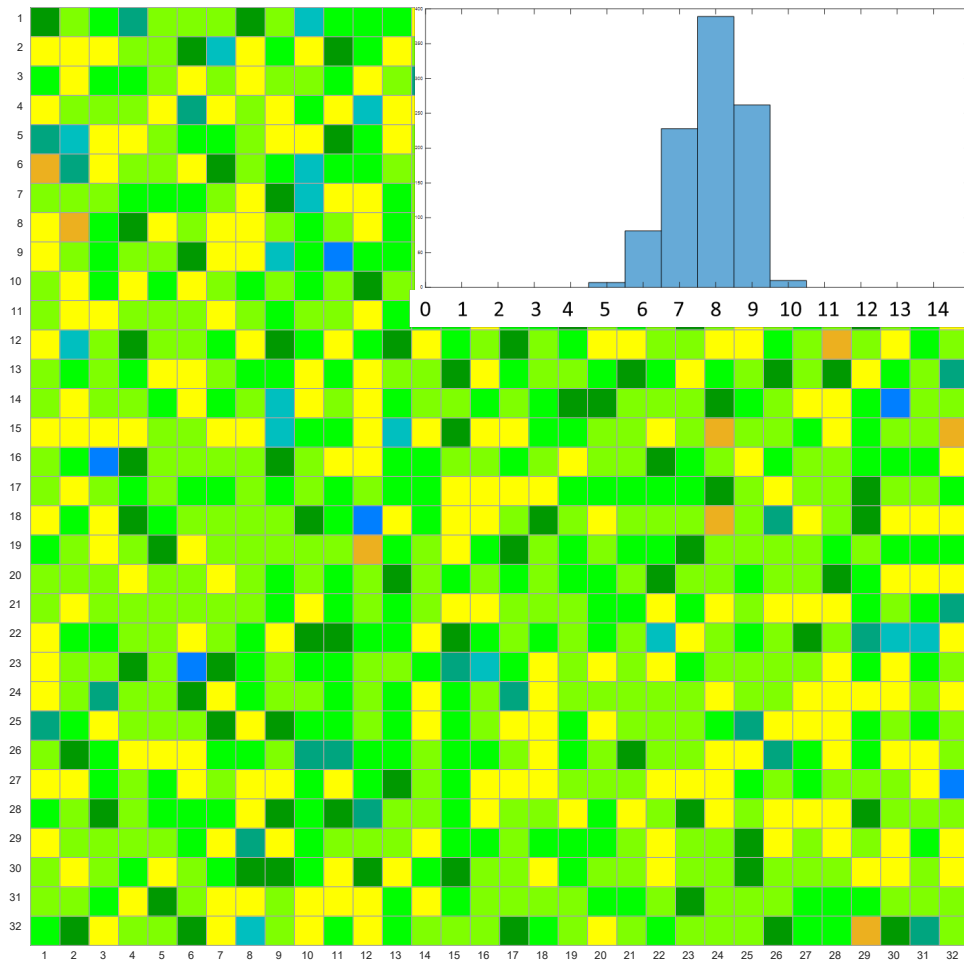
✓ Low-threshold operation



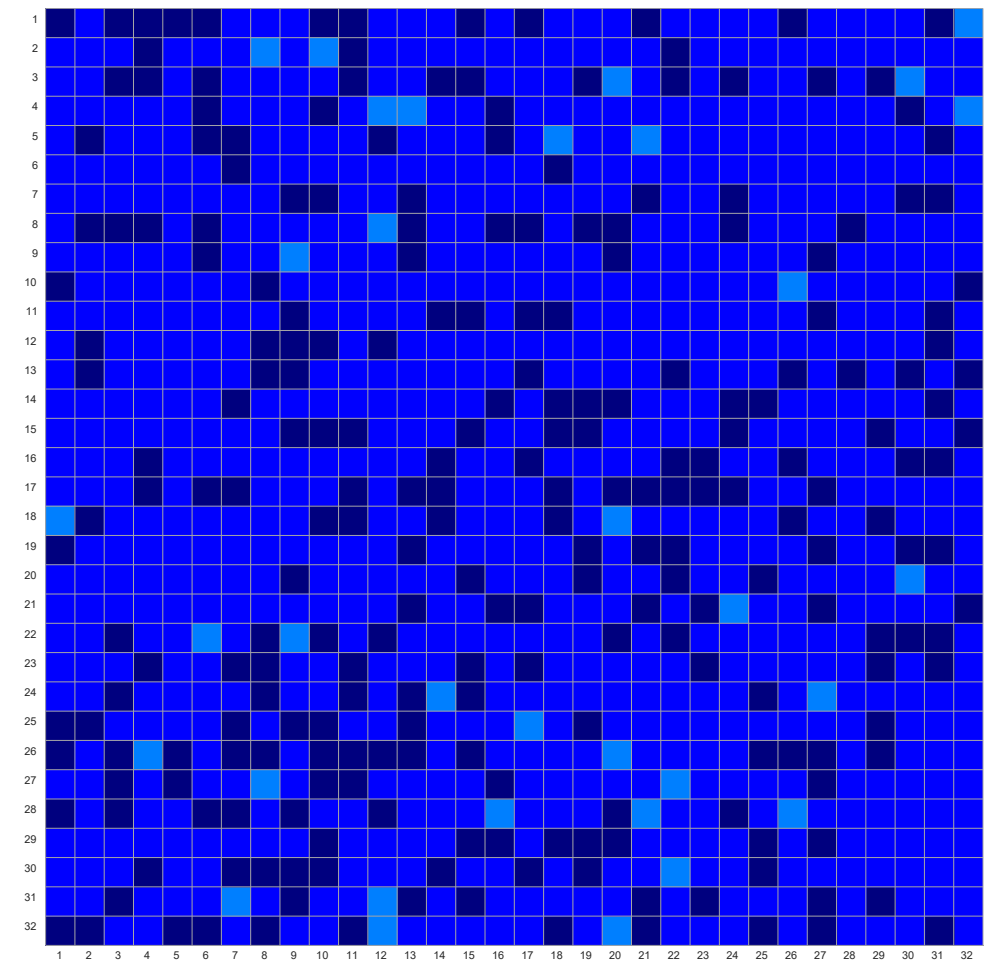
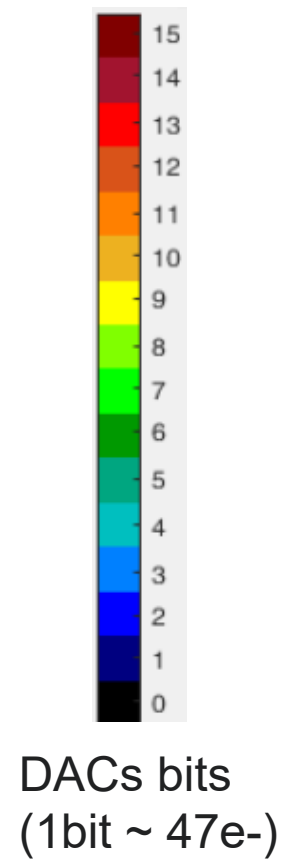
✓ All pixels are configurable and readable





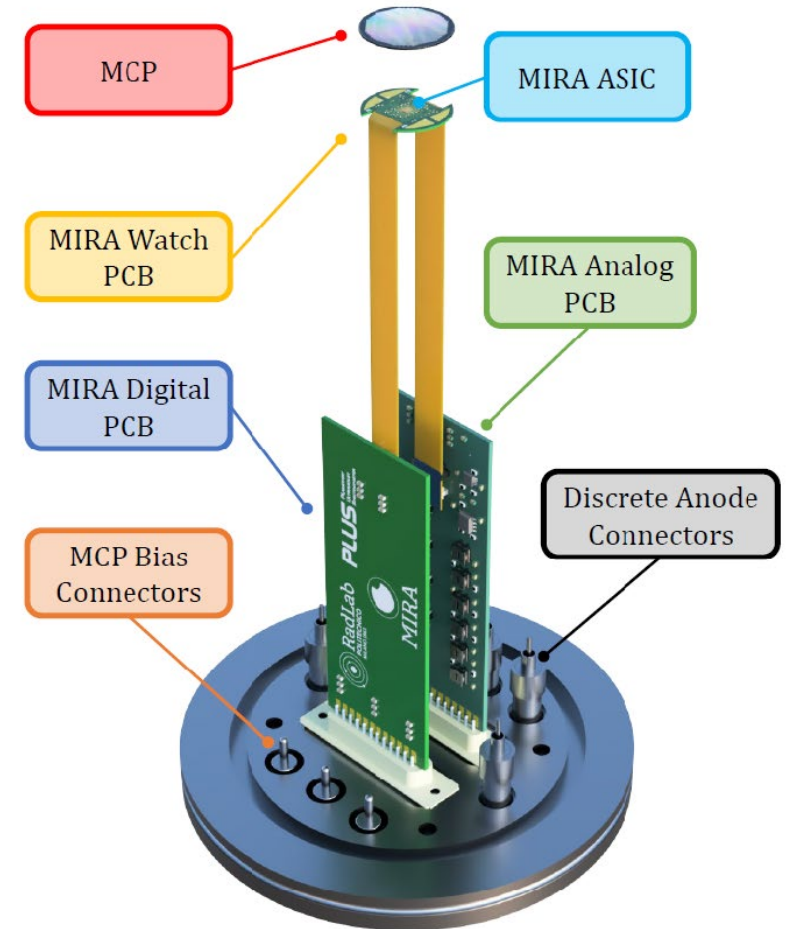
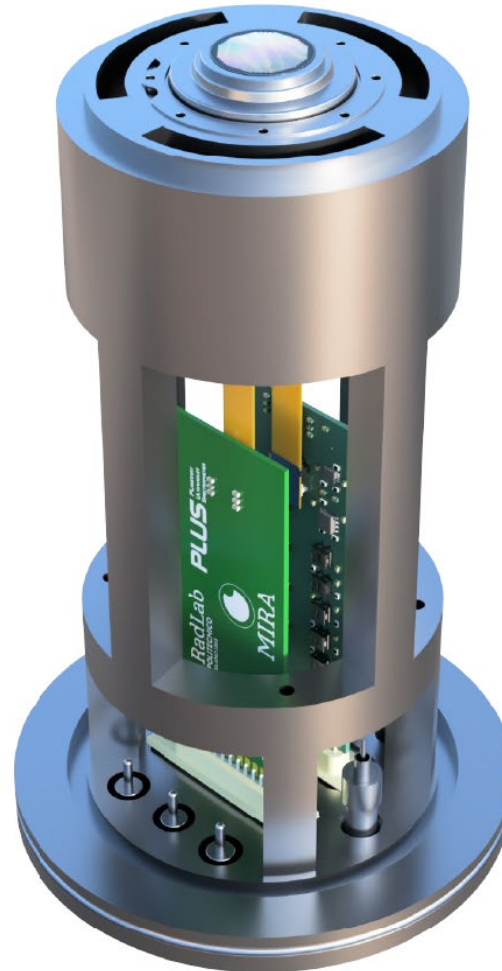
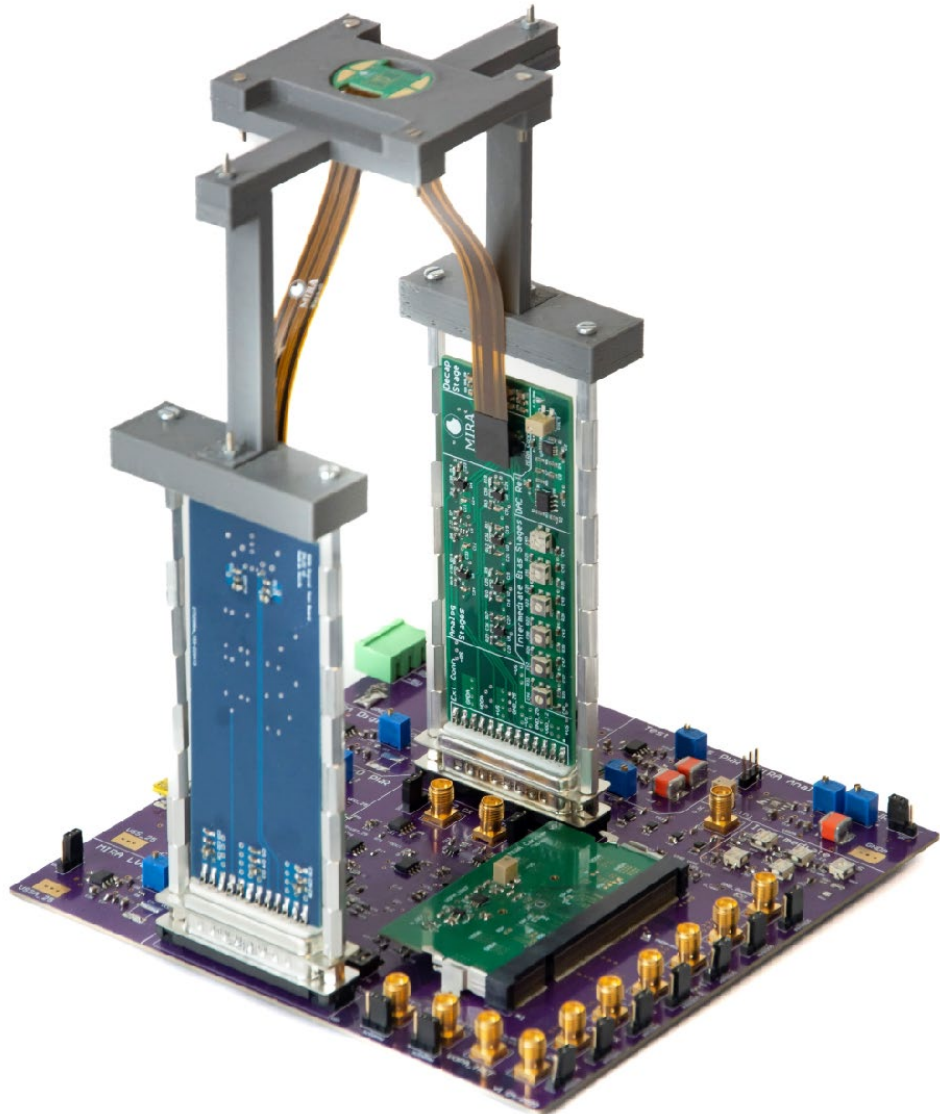


Offset dispersion (before calibration)



Noise threshold distribution after Offset calibration

# MIRA ASIC assembly in the MCP system



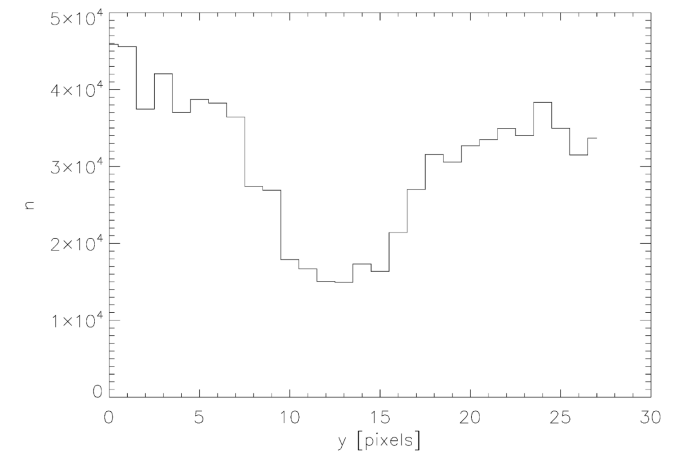
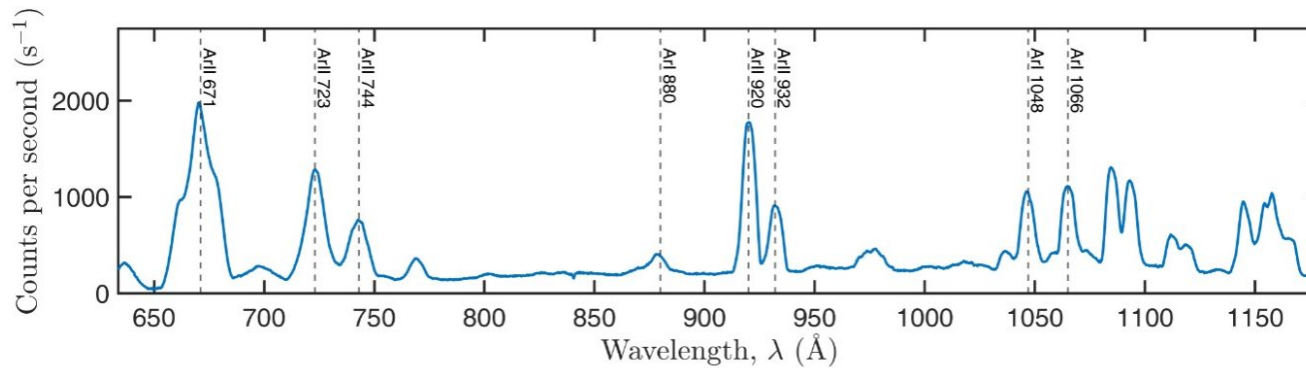
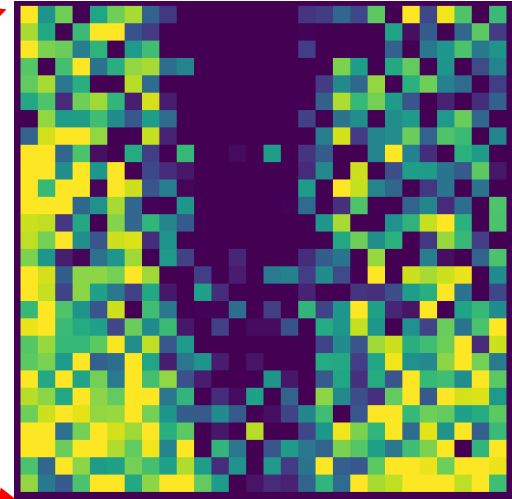
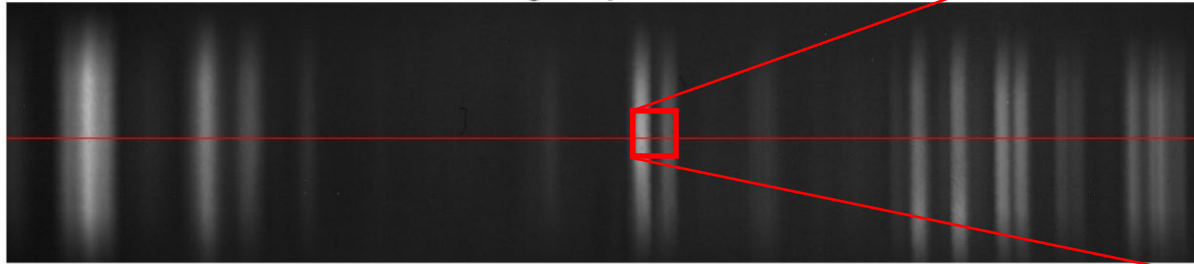
# MIRA MCP detector integration





# MIRA MCP detector acquisition

Argon Spectrum



MIRA ASIC developed for the readout of MCP for space applications:

- TSMC 65 nm technology
- 32 x 32 pixels, in a chip area of 2 mm x 2 mm, Active area of 1.12 mm x 1.12 mm
- Pixel size of **35  $\mu\text{m}$**
- **Low noise  $\rightarrow$  ENC  $\simeq$  20  $e^-_{\text{rms}}$**
- **MIRA II** prototype integrated with MCP

Future Developments:

- Extended characterization of the PLUS photon counting unit and MIRA II in the PLUS spectrometer with a UV source
- Revision of power consumption (presently  $\sim 150\mu\text{W}/\text{pixel}$ )
- Increase of ASIC pixels matrix (e.g. 256 $\times$ 256 pixels) and possible sub-pixel spatial resolution
- Possible extension of application for solid-state detectors?

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